GigaDevice Semiconductor Inc.

GD32F207xx Arm® Cortex®-M3 32-bit MCU

Datasheet

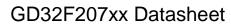


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1. General description

The GD32F207xx device belongs to the performance line of GD32 MCU Family. It is a new 32-bit general-purpose microcontroller based on the Arm® Cortex®-M3 RISC core with best cost-performance ratio in terms of processing capacity, reduced power consumption and peripheral set. The Cortex®-M3 is a next generation processor core which is tightly coupled with a Nested Vectored Interrupt Controller (NVIC), SysTick timer and advanced debug support.

The GD32F207xx device incorporates the Arm® Cortex®-M3 32-bit processor core operating at 120 MHz frequency with flash accesses zero wait states to obtain maximum efficiency. It provides up to 3072 KB on-chip flash memory and 256 KB SRAM memory. An extensive range of enhanced I/Os and peripherals connected to two APB buses. The devices offer up to three 12-bit 2 MSPS ADCs, two 12-bit DACs, up to ten 16-bit general timers, two 16-bit basic timers plus two 16-bit PWM advanced timers, as well as standard and advanced communication interfaces: up to three SPIs, three I2Cs, four USARTs and four UARTs, two I2Ss, two CANs, a SDIO, a USBFS and an Ethernet. Additional peripherals as TFT-LCD Interface (TLI), EXMC interface with SDRAM extension support, Digital camera interface (DCI), Cryptographic acceleration unit (CAU), Hash acceleration unit (HAU), True random number generator (TRNG) are included.

The device operates from a 2.6 to 3.6V power supply and available in -40 to +85 °C temperature range. Several power saving modes provide the flexibility for maximum optimization of power consumption, an especially important consideration in low power applications.

The above features make GD32F207xx devices suitable for a wide range of interconnection and advanced applications, especially in areas such as industrial control, consumer and handheld equipment, embedded modules, human machine interface, security and alarm systems, POS and electronic payment, automotive navigation and so on.





2. Device overview

2.1. Device information

Table 2-1. GD32F207xx devices features and peripheral list

Part Number					<u> </u>	2F207xx			
	Part Number	RC	RE	RG	RK	vc	VE	VG	VK
ч	Fast area (KB)	256	512	384	384	256	512	384	384
-lash	Normal area (KB)	0	0	640	2688	0	0	640	2688
_	Total (KB)	256	512	1024	3072	256	512	1024	3072
	SRAM (KB)	128	128	256	256	128	128	256	256
	General timer(16-	10	10	10	10	10	10	10	10
	bit)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)
	Advanced timer	2	2	2	2	2	2	2	2
	(16-bit)	(0,7)	(0,7)	(0,7)	(0,7)	(0,7)	(0,7)	(0,7)	(0,7)
Timers	SysTick	1	1	1	1	1	1	1	1
Ē	Basic timer (16-	2	2	2	2	2	2	2	2
	bit)	(5,6)	(5,6)	(5,6)	(5,6)	(5,6)	(5,6)	(5,6)	(5,6)
	Watchdog	2	2	2	2	2	2	2	2
	RTC	1	1	1	1	1	1	1	1
	USART	4	4	4	4	4	4	4	4
	UART	2	2	2	2	4	4	4	4
		(3-4)	(3-4)	(3-4)	(3-4)	(3-4,6-7)	(3-4,6-7)	(3-4,6-7)	(3-4,6-7)
	I2C	3	3	3	3	3	3	3	3
	SPI/I2S	3/2	3/2	3/2	3/2	3/2	3/2	3/2	3/2
>		(0-2)/(1-2)	(0-2)/(1-2)	(0-2)/(1-2)	(0-2)/(1-2)	(0-2)/(1-2)	(0-2)/(1-2)	(0-2)/(1-2)	(0-2)/(1-2)
ctivit	SDIO	1	1	1	1	1	1	1	1
Connectivity	CAN	2	2	2	2	2	2	2	2
O	USBFS	1	1	1	1	1	1	1	1
	ENET	1	1	1	1	1	1	1	1
	TLI	0	0	0	0	1	1	1	1
	DCI	1	1	1	1	1	1	1	1
	CAU/HAU	1	1	1	1	1	1	1	1
	GPIO	51	51	51	51	82	82	82	82
	EXMC/SDRAM	0/0	0/0	0/0	0/0	1/0	1/0	1/0	1/0



5.41	GD32F207xx								
Part Number	RC	RE	RG	RK	VC	VE	VG	VK	
ADC (CHs)	3(16)	3(16)	3(16)	3(16)	3(16)	3(16)	3(16)	3(16)	
DAC	2	2	2	2	2	2	2	2	
Package		LQI	FP64			LQF	P100		

Table 2-1. GD32F207xx devices features and peripheral list (continued)

Part Number					D32F207xx	-	,	
	Part Number	ZC	ZE	ZG	ZK	IE	IG	IK
	Code area (KB)	256	512	384	384	512	384	384
Flash	Data area (KB)	0	0	640	2688	0	640	2688
_	Total (KB)	256	512	1024	3072	512	1024	3072
	SRAM (KB)	128	128	256	256	128	256	256
	General timer	10	10	10	10	10	10	10
	(16-bit)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)	(1-4,8-13)
	Advanced timer	2	2	2	2	2	2	2
	(16-bit)	(0,7)	(0,7)	(0,7)	(0,7)	(0,7)	(0,7)	(0,7)
Timers	SysTick	1	1	1	1	1	1	1
Ē	Basic timer (16-	2	2	2	2	2	2	2
	bit)	(5,6)	(5,6)	(5,6)	(5,6)	(5,6)	(5,6)	(5,6)
	Watchdog	2	2	2	2	2	2	2
	RTC	1	1	1	1	1	1	1
	USART	4	4	4	4	4	4	4
	UART	4	4	4	4	4	4	4
	I2C	3	3	3	3	3	3	3
	SPI/I2S	3/2	3/2	3/2	3/2	3/2	3/2	3/2
/ity	SDIO	1	1	1	1	1	1	1
Connectivity	CAN	2	2	2	2	2	2	2
Con	USBFS	1	1	1	1	1	1	1
	ENET	1	1	1	1	1	1	1
	TLI	1	1	1	1	1	1	1
	DCI	1	1	1	1	1	1	1
	CAU/HAU	1	1	1	1	1	1	1
	GPIO	114	114	114	114	140	140	140



5 (1)	GD32F207xx								
Part Number	ZC	ZE	ZG	ZK	IE	IG	IK		
EXMC/SDRAM	1/1	1/1	1/1	1/1	1/1	1/1	1/1		
ADC (CHs)	3(24)	3(24)	3(24)	3(24)	3(24)	3(24)	3(24)		
DAC	2	2	2	2	2	2	2		
Package		LQFI	⊃144	LQFP176					



2.2. Block diagram

SW/JTAG TPIU POR/PDR Flash Flash IBus ARM Cortex-M3 Memory Memory Processor Fmax:120MHz Fmax:120MHz Controller DBus EXMC SRAM0 SRAM1 LDO 1.2V Master NVIC SRAM2 IRC 8MHz ₽HB CAU HAU TRNG DCI DMA0(7 chs) AHB2 Peripherals DMA1(7 chs) SDIO USBFS CRC RCU HXTAL 3-25MHz ENET AHB1 Peripherals AHB to APB Bridge2 | AHB to APB Bridge1 ΤЦ LVD Interrput request Powered By VDDA WWDGT USART0 FWDGT SPI0 RTC SAR ADC ADC0~2 Powered By VDDA DAC EXTI CAN0 GPIOA GPIOB CAN1 SPI1~2 **GPIOC** GPIOD TIMER1~3 ◀ TIMER4~6 GPIOE TIMER **GPIOF** 11~13 **GPIOG** USART1~2 TIMER0 UART3~4 TIMER7 UART6~7 TIMER8~10 I2C0 USART5 I2C1 GPIOH I2C2 GPIOI

Figure 2-1. GD32F207xx block diagram



2.3. Pinouts and pin assignment

Figure 2-2. GD32F207Ix LQFP176 pinouts





Figure 2-3. GD32F207Zx LQFP144 pinouts

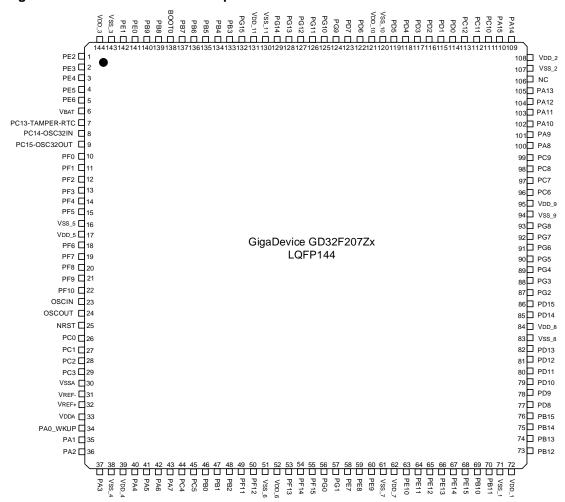




Figure 2-4. GD32F207Vx LQFP100 pinouts

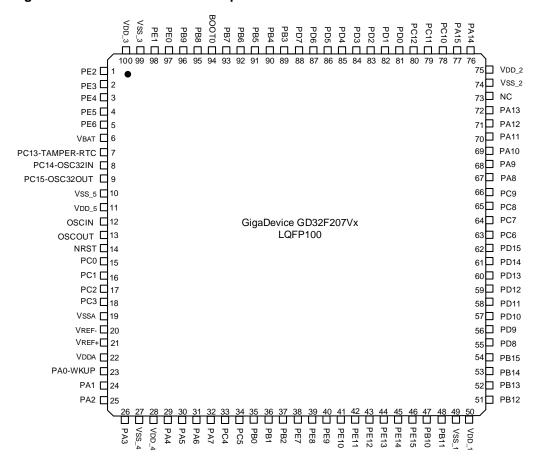
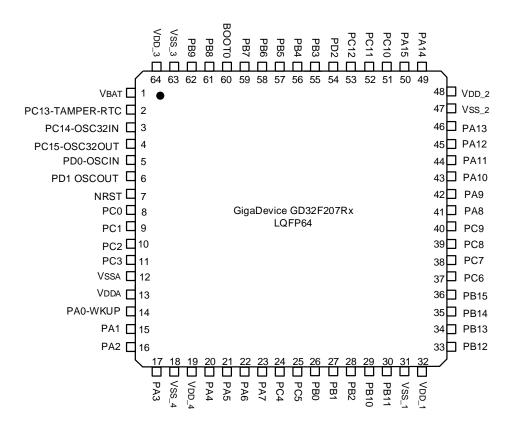




Figure 2-5. GD32F207Rx LQFP64 pinouts





2.4. Memory map

Table 2-2. GD32F207xx memory map

Pre-defined Regions	Bus	Address	Peripherals
		0xC000 0000 - 0xDFFF FFFF	EXMC - SDRAM
External		0xA000 1000 - 0xBFFF FFFF	Reserved
Device	ALID	0xA000 0000 - 0xA000 0FFF	EXMC - SWREG
	AHB	0x9000 0000 - 0x9FFF FFFF	EXMC - PC CARD
External		0x7000 0000 - 0x8FFF FFFF	EXMC - NAND
RAM		0x6000 0000 - 0x6FFF FFFF	EXMC - NOR/PSRAM/SRAM
		0x5006 0C00 - 0x5FFF FFFF	Reserved
		0x5006 0800 - 0x5006 0BFF	TRNG
		0x 5006 0400 – 0x5006 07FF	HAU
	AHB2	0x 5006 0000 – 0x5006 03FF	CAU
		0x5005 0400 - 0x5005 FFFF	Reserved
		0x5005 0000 - 0x5005 03FF	DCI
		0x5004 0000 - 0x5004 FFFF	Reserved
	Alle	0x5000 0000 - 0x5003 FFFF	USBFS
		0x4002 A000 - 0x4FFF FFFF	Reserved
		0x4002 8000 - 0x4002 9FFF	ENET
		0x4002 3400 - 0x4002 7FFF	Reserved
		0x4002 3000 - 0x4002 33FF	CRC
		0x4002 2400 - 0x4002 2FFF	Reserved
		0x4002 2000 - 0x4002 23FF	FMC
	AHB1	0x4002 1400 - 0x4002 1FFF	Reserved
Peripheral		0x4002 1000 - 0x4002 13FF	RCU
		0x4002 0800 - 0x4002 0FFF	Reserved
		0x4002 0400 - 0x4002 07FF	DMA0
		0x4002 0000 - 0x4002 03FF	DMA1
		0x4001 8400 - 0x4001 FFFF	Reserved
		0x4001 8000 - 0x4001 83FF	SDIO
		0x4001 7C00 - 0x4001 7FFF	Reserved
		0x4001 7800 - 0x4001 7BFF	GPIOI
		0x4001 7400 - 0x4001 77FF	GPIOH
		0x4001 7000 - 0x4001 73FF	USART5
	ADDO	0x4001 6C00 - 0x4001 6FFF	Reserved
	APB2	0x4001 6800 - 0x4001 6BFF	TLI
		0x4001 5800 - 0x4001 67FF	Reserved
		0x4001 5400 - 0x4001 57FF	TIMER10
		0x4001 5000 - 0x4001 53FF	TIMER9
		0x4001 4C00 - 0x4001 4FFF	TIMER8



Pre-defined			Zi Zur XX Datasiice
Regions	Bus	Address	Peripherals
_		0x4001 4000 - 0x4001 4BFF	Reserved
		0x4001 3C00 - 0x4001 3FFF	ADC2
		0x4001 3800 - 0x4001 3BFF	USART0
		0x4001 3400 - 0x4001 37FF	TIMER7
		0x4001 3000 - 0x4001 33FF	SPI0
		0x4001 2C00 - 0x4001 2FFF	TIMER0
		0x4001 2800 - 0x4001 2BFF	ADC1
		0x4001 2400 - 0x4001 27FF	ADC0
		0x4001 2000 - 0x4001 23FF	GPIOG
		0x4001 1C00 - 0x4001 1FFF	GPIOF
		0x4001 1800 - 0x4001 1BFF	GPIOE
		0x4001 1400 - 0x4001 17FF	GPIOD
		0x4001 1000 - 0x4001 13FF	GPIOC
		0x4001 0C00 - 0x4001 0FFF	GPIOB
		0x4001 0800 - 0x4001 0BFF	GPIOA
		0x4001 0400 - 0x4001 07FF	EXTI
		0x4001 0000 - 0x4001 03FF	AFIO
		0x4000 C400 - 0x4000 FFFF	Reserved
		0x4000 C000 - 0x4000 C3FF	I2C2
		0x4000 8000 - 0x4000 BFFF	Reserved
		0x4000 7C00 - 0x4000 7FFF	UART7
		0x4000 7800 - 0x4000 7BFF	UART6
		0x4000 7400 - 0x4000 77FF	DAC
		0x4000 7000 - 0x4000 73FF	PMU
		0x4000 6C00 - 0x4000 6FFF	BKP
		0x4000 6800 - 0x4000 6BFF	CAN1
		0x4000 6400 - 0x4000 67FF	CAN0
		0x4000 5C00 - 0x4000 63FF	USB/CAN shared
	APB1	0x4000 5800 - 0x4000 5BFF	I2C1
		0x4000 5400 - 0x4000 57FF	I2C0
		0x4000 5000 - 0x4000 53FF	UART4
		0x4000 4C00 - 0x4000 4FFF	UART3
		0x4000 4800 - 0x4000 4BFF	USART2
		0x4000 4400 - 0x4000 47FF	USART1
		0x4000 4000 - 0x4000 43FF	Reserved
		0x4000 3C00 - 0x4000 3FFF	SPI2/I2S2
		0x4000 3800 - 0x4000 3BFF	SPI1/I2S1
		0x4000 3400 - 0x4000 37FF	Reserved
		0x4000 3000 - 0x4000 33FF	FWDGT
		0x4000 2C00 - 0x4000 2FFF	WWDGT

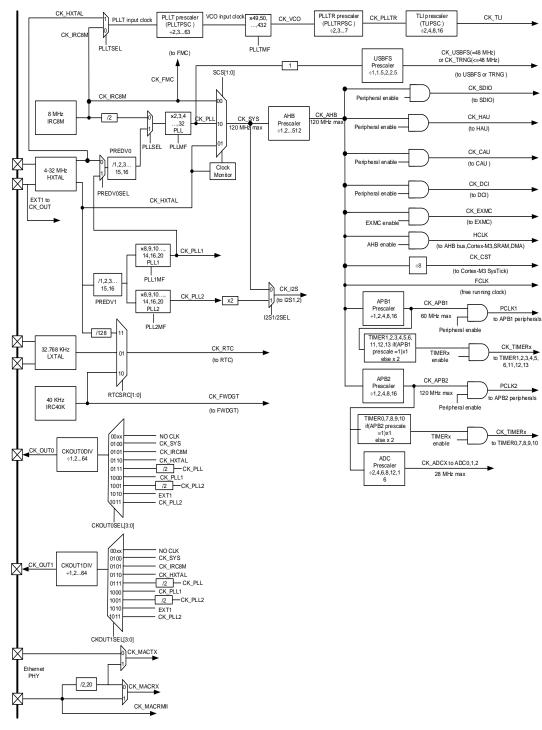


			ZI ZOTAX Datasileet
Pre-defined Regions	Bus	Address	Peripherals
		0x4000 2800 - 0x4000 2BFF	RTC
		0x4000 2400 - 0x4000 27FF	Reserved
		0x4000 2000 - 0x4000 23FF	TIMER13
		0x4000 1C00 - 0x4000 1FFF	TIMER12
		0x4000 1800 - 0x4000 1BFF	TIMER11
		0x4000 1400 - 0x4000 17FF	TIMER6
		0x4000 1000 - 0x4000 13FF	TIMER5
		0x4000 0C00 - 0x4000 0FFF	TIMER4
		0x4000 0800 - 0x4000 0BFF	TIMER3
		0x4000 0400 - 0x4000 07FF	TIMER2
		0x4000 0000 - 0x4000 03FF	TIMER1
		0x2004 0000 - 0x3FFF FFFF	Reserved
SRAM	AHB	0x2002 0000 - 0x2003 FFFF	SRAM2(128KB)
SKAW		0x2001 C000 - 0x2001 FFFF	SRAM1(16KB)
		0x2000 0000 - 0x2001 BFFF	SRAM0(112KB)
		0x1FFF F810 - 0x1FFF FFFF	Reserved
		0x1FFF F800 - 0x1FFF F80F	Option Bytes
		0x1FFF B000 - 0x1FFF F7FF	System memory
Code	AHB	0x0830 0000 - 0x1FFF AFFF	Reserved
Code	ALID	0x0800 0000 - 0x082F FFFF	Main Flash(3072KB)
			Aliased to Flash or system
		0x0000 0000 - 0x07FF FFFF	memory according to BOOT pins configuration



2.5. Clock tree

Figure 2-6. GD32F207xx clock tree



Legend:

HXTAL: High speed crystal oscillator LXTAL: Low speed crystal oscillator IRC8M: Internal 8M RC oscillators IRC40K: Internal 40K RC oscillator

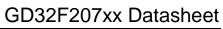


2.6. Pin definitions

2.6.1. GD32F207lx LQFP176 pin definitions

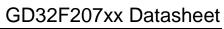
Table 2-3. GD32F207Ix LQFP176 pin definitions

Pin	0. 0	Pin	1/0	P176 pin definitions
Name	Pins		Level ⁽²⁾	Functions description
Name		Type	Leven	D () DE0
550			5) (T	Default: PE2
PE2	1	I/O	5VT	Alternate: TRACECK, EXMC_A23
				Remap: ENET_MII_TXD3
PE3	2	I/O	5VT	Default: PE3
				Alternate: TRACED0, EXMC_A19
		.,,		Default: PE4
PE4	3	I/O	5VT	Alternate:TRACED1, EXMC_A20
				Remap: DCI_D4, TLI_B0
555			5) (T	Default: PE5
PE5	4	I/O	5VT	Alternate:TRACED2, EXMC_A21
				Remap: TIMER8_CH0, DCI_D6, TLI_G0
550	_		5) (T	Default: PE6
PE6	5	I/O	5VT	Alternate:TRACED3, EXMC_A22
.,				Remap: TIMER8_CH1, DCI_D7, TLI_G1
VBAT	6	Р		Default: VBAT
PI8	7	I/O		Default: PI8
PC13-				Default: PC13
TAMPE	8	I/O	5VT	Alternate: TAMPER-RTC
R-RTC				Allomato. Train Entrito
PC14-				Defaults DC44
OSC32	9	I/O		Default: PC14 Alternate: OSC32IN
IN				Alternate. OSC32IIV
PC15-				
OSC32	10	I/O		Default: PC15
OUT				Alternate: OSC32OUT
				Default: PI9
PI9	11	I/O	5VT	Alternate: EXMC_D30
				Remap: TLI_VSYNC, CAN0_RX
				Default: PI10
PI10	12	I/O	5VT	Alternate: EXMC_D31
				Remap: TLI_HSYNC, ENET_MII_RX_ER
PI11	13	I/O	5VT	Default: PI11
Vss	14	Р		Default: Vss
V _{DD}	15	Р		Default: V _{DD}
55				Default: PF0
PF0	16	I/O	5VT	Alternate: EXMC_A0
				Remap: I2C1_SDA
PF1	17	I/O	5VT	Default: PF1
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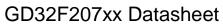


				GD32F207XX Datastieet			
Pin	Pins	Pin	I/O	Functions description			
Name		Type ⁽¹⁾	Level ⁽²⁾				
				Alternate: EXMC_A1			
				Remap: I2C1_SCL			
				Default: PF2			
PF2	18	I/O	5VT	Alternate: EXMC_A2			
				Remap: I2C1_SMBA			
DEO	10	1/0	C) /T	Default: PF3			
PF3	19	I/O	5VT	Alternate: EXMC_A3, ADC2_IN9			
DE4	20	1/0	C) /T	Default: PF4			
PF4	20	1/0	5VT	Alternate: EXMC_A4, ADC2_IN14			
DEC	0.4	1/0	5\ /T	Default: PF5			
PF5	21	I/O	5VT	Alternate: EXMC_A5, ADC2_IN15			
V _{SS_5}	22	Р		Default: V _{SS_5}			
V _{DD_5}	23	Р		Default: V _{DD} 5			
				Default: PF6			
PF6	24	I/O		Alternate: ADC2_IN4, EXMC_NIORD			
		., 0		Remap: TIMER9_CH0, UART6_RX			
				Default: PF7			
PF7	25	I/O		Alternate: ADC2_IN5, EXMC_NREG			
' ' '	20	1,0		Remap: TIMER10_CH0, UART6_TX			
				Default: PF8			
PF8	26	I/O		Alternate: ADC2_IN6, EXMC_NIOWR			
110	20	1/0		Remap: TIMER12_CH0			
				Default: PF9			
PF9	27	I/O		Alternate: ADC2_IN7, EXMC_CD			
FF9	21	1/0		Remap: TIMER13_CH0			
				Default: PF10			
PF10	28	I/O		Alternate: ADC2_IN8, EXMC_INTR			
1110	20	1/0		Remap: DCI_D11, TLI_DE			
				Default: OSCIN			
OSCIN	29	I		Remap: PD0, PH0			
0000							
osco	30	0		Default: OSCOUT			
UT				Remap: PD1, PH1			
NRST	31	I/O		Default: NRST			
				Default: PC0			
PC0	32	I/O		Alternate: ADC012_IN10			
				Remap: EXMC_SDNWE			
PC1	33	I/O		Default: PC1			
	-	., 0		Alternate: ADC012_IN11, ENET_MDC			
				Default: PC2			
PC2	34	I/O		Alternate: ADC012_IN12, ENET_MII_TXD2			
				Remap: EXMC_SDNE0, SPI1_MISO			
				Default: PC3			
PC3	35	I/O		Alternate: ADC012_IN13, ENET_MII_TX_CLK			
				Remap: EXMC_SDCKE0, SPI1_MOSI, I2S1_SD			
Vssa	36	Р		Default: V _{SSA}			



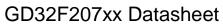


	GD32F207XX Datastieet					
Pin	Pins	Pin	I/O	Functions description		
Name		Type ⁽¹⁾	Level ⁽²⁾	·		
V _{REF} -	37	Р		Default: V _{REF} -		
V _{REF+}	38	Р		Default: V _{REF+}		
V_{DDA}	39	Р		Default: V _{DDA}		
				Default: PA0		
PA0-	4.0			Alternate: WKUP, USART1_CTS, ADC012_IN0, TIMER1_CH0,		
WKUP	40	I/O		TIMER1_ETI, TIMER4_CH0, TIMER7_ETI, ENET_MII_CRS		
				Remap: UART3_TX		
				Default: PA1		
D 4 4	١.,	1/0		Alternate: USART1_RTS, ADC012_IN1, TIMER1_CH1,		
PA1	41	I/O		TIMER4_CH1,ENET_MII_RX_CLK, ENET_RMII_REF_CLK		
				Remap: UART3_RX		
				Default: PA2		
PA2	42	I/O		Alternate: USART1_TX, ADC012_IN2, TIMER1_CH2,		
				TIMER4_CH2, TIMER8_CH0, ENET_MDIO, SPI0_IO3		
				Default: PH2		
PH2	43	I/O	5VT	Alternate: EXMC_SDCKE0		
				Remap: TLI_R0, ENET_MII_CRS		
				Default: PH3		
PH3	44	I/O	5VT	Alternate: EXMC_SDNE0		
				Remap: TLI_R1, ENET_MII_COL		
5114	4-		5) (T	Default: PH4		
PH4	45	I/O	5VT	Remap: I2C1_SCL, TLI_R0		
				Default: PH5		
PH5	46	I/O	5VT	Alternate: EXMC_SDNWE		
				Remap: I2C1_SDA		
				Default: PA3		
540				Alternate: USART1_RX, ADC012_IN3, TIMER1_CH3,		
PA3	47	I/O		TIMER4_CH3, TIMER8_CH1, ENET_MII_COL, SPI0_IO4		
				Remap: TLI_B5		
Vss_4	48	Р		Default: V _{SS_4}		
V _{DD_4}	49	Р		Default: V _{DD 4}		
				Default: PA4		
				Alternate: SPI0_NSS, USART1_CK, DAC_OUT0, ADC01_IN4,		
PA4	50	I/O		DCI_HSYNC		
				Remap: SPI2_NSS, I2S2_WS, TLI_VSYNC		
				Default: PA5		
PA5	51	I/O		Alternate: SPI0_SCK, ADC01_IN5, DAC_OUT1		
				Remap: TIMER1_CH0, TIMER1_ETI, TIMER7_CH0_ON		
				Default: PA6		
				Alternate: SPI0_MISO, ADC01_IN6, TIMER2_CH0,		
PA6	52	I/O		TIMER7_BRKIN, TIMER12_CH0, DCI_PIXCLK		
				Remap: TIMER0_BRKIN, TLI_G2		
				Default: PA7		
PA7	53	I/O		Alternate: SPI0_MOSI, ADC01_IN7, TIMER2_CH1,		
				TIMER7_CH0_ON, TIMER13_CH0, ENET_MII_RX_DV,		



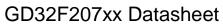


				GD32F207XX Datastieet		
Pin	Pins	Pin	I/O	Functions description		
Name		Type ⁽¹⁾	Level ⁽²⁾	. unonono ussanpuon		
				ENET_RMII_CRS_DV		
				Remap: TIMER0_CH0_ON		
PC4	54	I/O		Default: PC4		
PC4	54	1/0		Alternate: ADC01_IN14, ENET_MII_RXD0. ENET_RMII_RXD0		
DOE	- F	I/O		Default: PC5		
PC5	55	1/0		Alternate: ADC01_IN15, ENET_MII_RXD1, ENET_RMII_RXD1		
				Default: PB0		
DDO		1/0		Alternate: ADC01_IN8, TIMER2_CH2, TIMER7_CH1_ON,		
PB0	56	I/O		ENET_MII_RXD2		
				Remap: TIMER0_CH1_ON, TLI_R3		
				Default: PB1		
DD4		1/0		Alternate: ADC01_IN9, TIMER2_CH3, TIMER7_CH2_ON,		
PB1	57	I/O		ENET_MII_RXD3		
				Remap: TIMER0_CH2_ON, TLI_R6		
PB2	58	I/O	5VT	Default: PB2, BOOT1		
				Default: PF11		
PF11	59	I/O	5VT	Alternate: EXMC_NIOS16, DCI_D12, EXMC_SDNRAS		
				Default: PF12		
PF12	60	I/O	5VT	Alternate: EXMC_A6		
Vss_6	61	Р		Default: Vss_6		
V _{DD_6}	62	Р		Default: V _{DD 6}		
1 00_0		•		Default: PF13		
PF13	63	I/O	5VT	Alternate: EXMC A7		
				Default: PF14		
PF14	64	I/O	5VT	Alternate: EXMC A8		
				Default: PF15		
PF15	65	I/O	5VT	Alternate: EXMC_A9		
				Default: PG0		
PG0	66	I/O	5VT	Alternate: EXMC_A10		
				Default: PG1		
PG1	67	I/O	5VT	Alternate: EXMC_A11		
				Default: PE7		
PE7	68	I/O	5VT	Alternate: EXMC_D4, UART6_RX		
				Remap: TIMER0_ETI		
				Default: PE8		
PE8	69	I/O	5VT	Alternate: EXMC_D5, UART6_TX		
				Remap: TIMER0_CH0_ON		
				Default: PE9		
PE9	70	I/O	5VT	Alternate: EXMC_D6		
				Remap: TIMER0_CH0		
Vss_7	71	Р		Default: Vss_7		
V _{DD_7}	72	Р		Default: V _{DD 7}		
100_1	<u> </u>	•		Default: PE10		
PE10	73	I/O	5VT	Alternate: EXMC_D7		
10		"		Remap: TIMER0_CH1_ON		
	1		1	• = =		



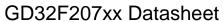


				GD32F207XX Datasileet	
Pin	Pins	Pin	I/O	Functions description	
Name		Type ⁽¹⁾	Level ⁽²⁾	- unonono doscription	
				Default: PE11	
PE11	74	I/O	5VT	Alternate: EXMC_D8	
				Remap: TIMER0_CH1, TLI_G3	
				Default: PE12	
PE12	75	I/O	5VT	Alternate: EXMC_D9	
				Remap: TIMER0_CH2_ON, TLI_B4	
				Default: PE13	
PE13	76	I/O	5VT	Alternate: EXMC_D10	
				Remap: TIMER0_CH2, TLI_DE	
				Default: PE14	
PE14	77	I/O	5VT	Alternate: EXMC_D11	
				Remap: TIMER0_CH3, TLI_ PIXCLK	
				Default: PE15	
PE15	78	I/O	5VT	Alternate: EXMC_D12	
				Remap: TIMER0_BRKIN, TLI_R7	
				Default: PB10	
PB10	79	I/O	5VT	Alternate: I2C1_SCL, USART2_TX, ENET_MII_RX_ER	
				Remap: TIMER1_CH2, TLI_G4, SPI1_SCK, I2S1_CK	
				Default: PB11	
PB11	80	I/O	5VT	Alternate: I2C1_SDA, USART2_RX, ENET_MII_TX_EN,	
'	00	1/0	3 7 1	ENET_RMII_TX_EN	
				Remap: TIMER1_CH3, TLI_G5	
Vss_1	81	Р		Default: V _{SS_1}	
V_{DD_1}	82	Р		Default: V _{DD_1}	
			Default: PH6		
PH6	83	I/O	5VT	Alternate: EXMC_SDNE1	
				Remap: I2C1_SMBA, TIMER11_CH0, ENET_MII_RXD2, DCI_D8	
				Default: PH7	
PH7	84	I/O	5VT	Alternate: EXMC_SDCKE1	
				Remap: I2C2_SCL, ENET_MII_RXD3, DCI_D9	
				Default: PH8	
PH8	85	I/O	5VT	Alternate: EXMC_D16	
				Remap: TLI_R2, I2C2_SDA, DCI_HSYNC	
				Default: PH9	
PH9	86	I/O	5VT	Alternate: EXMC_D17	
				Remap: TLI_R3, I2C2_SMBA, TIMER11_CH1, DCI_D0	
				Default: PH10	
PH10	87	I/O	5VT	Alternate: EXMC_D18	
				Remap: TLI_R4, TIMER4_CH0, DCI_D1	
				Default: PH11	
PH11	88	I/O	5VT	Alternate: EXMC_D19	
				Remap: TLI_R5, TIMER4_CH1, DCI_D2	
				Default: PH12	
PH12	89	I/O	5VT	Alternate: EXMC_D20	
				Remap: TLI_R6, TIMER4_CH2, DCI_D3	
Vss	V _{SS} 90 P Default: V _{SS}		Default: Vss		



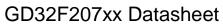


		I	I	GD32F207XX DataSheet		
Pin	Dina	Pin	I/O	Functions description		
Name	Pins	Type ⁽¹⁾	Level ⁽²⁾	Functions description		
V_{DD}	91	Р		Default: V _{DD}		
				Default: PB12		
PB12	92	I/O	5VT	Alternate: SPI1_NSS, I2C1_SMBA, USART2_CK, TIMER0_BRKIN,		
				I2S1_WS, CAN1_RX, ENET_MII_TXD0, ENET_RMII_TXD0		
				Default: PB13		
PB13	93	I/O	5VT	Alternate: SPI1_SCK, USART2_CTS, TIMER0_CH0_ON, I2S1_CK,		
				CAN1_TX , ENET_MII_TXD1, ENET_RMII_TXD1		
				Default: PB14		
PB14	94	I/O	5VT	Alternate: SPI1_MISO, USART2_RTS, TIMER0_CH1_ON,		
				TIMER11_CH0		
				Default: PB15		
PB15	95	I/O	5VT	Alternate: SPI1_MOSI, TIMER0_CH2_ON, I2S1_SD,		
				TIMER11_CH1		
				Default: PD8		
PD8	96	I/O	5VT	Alternate: EXMC_D13		
				Remap: USART2_TX, ENET_MII_RX_DV, ENET_RMII_CRS_DV		
				Default: PD9		
PD9	97	I/O	5VT	Alternate: EXMC_D14		
				Remap: USART2_RX, ENET_MII_RXD0, ENET_RMII_RXD0		
				Default: PD10		
PD10	98	I/O	5VT	Alternate: EXMC_D15		
1 5 10		.,,	011	Remap: USART2_CK, ENET_MII_RXD1, ENET_RMII_RXD1,		
				TLI_B3		
				Default: PD11		
PD11	99	I/O	5VT	Alternate: EXMC_A16		
	-			Remap: USART2_CTS, ENET_MII_RXD2		
				Default: PD12		
PD12	100	I/O	5VT	Alternate: EXMC_A17		
				Remap: TIMER3_CH0, USART2_RTS		
DD40	101	1/0	C) /T	Default: PD13		
PD13	101	I/O	5VT	Alternate: EXMC_A18		
	400	Б		Remap: TIMER3_CH1		
Vss_8	102	Р		Default: V _{SS_8}		
V _{DD_8}	103	Р		Default: V _{DD_8}		
5544	404	.,,	5) (T	Default: PD14		
PD14	104	I/O	5VT	Alternate: EXMC_D0		
	-			Remap: TIMER3_CH2		
DD45	405	1/0	5) (T	Default: PD15		
PD15	105	I/O	5VT	Alternate: EXMC_D1		
	-			Remap: TIMER3_CH3		
PG2	106	I/O	5VT	Default: PG2 Alternate: EXMC_A12		
				Default: PG3		
PG3	107	I/O	5VT	Alternate: EXMC_A13		
				Default: PG4		
PG4	108	I/O	5VT	Alternate: EXMC_A14, EXMC_BA0		
	1	l	l			



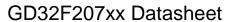


				GD32F207XX Datastiee	
Pin	Pins	Pin	1/0	Functions description	
Name		Type ⁽¹⁾	Level ⁽²⁾	p	
DOF	100	1/0	5\ /T	Default: PG5	
PG5	109	1/0	5VT	Alternate: EXMC_A15, EXMC_BA1	
				Default: PG6	
PG6	110	I/O	5VT	Alternate: EXMC_INT1	
				Remap: DCI_D12, TLI_R7	
				Default: PG7	
PG7	111	I/O	5VT	Alternate: EXMC_INT2, DCI_D13	
				Remap: USART5_CK, TLI_ PIXCLK	
				Default: PG8	
PG8	112	I/O	5VT	Alternate: EXMC_SDCLK, USART5_RTS	
				Remap: ENET_PPS_OUT	
Vss_9	113	Р		Default: Vss_9	
V _{DD_9}	114	Р		Default: V _{DD 9}	
				Default: PC6	
PC6	115	I/O	5VT	Alternate: I2S1_MCK, TIMER7_CH0, SDIO_D6, USART5_TX	
		., C		Remap: TIMER2_CH0, DCI_D0, TLI_HSYNC	
				Default: PC7	
PC7	116	I/O	5VT	Alternate: I2S2_MCK, TIMER7_CH1, SDIO_D7, USART5_RX	
		., 0	011	Remap: TIMER2_CH1, DCI_D1, TLI_G6	
				Default: PC8	
PC8	117	I/O	5VT	Alternate: TIMER7_CH2, SDIO_D0, DCI_D2, USART5_CK	
1 00		1,0	011	Remap: TIMER2_CH2	
				Default: PC9	
PC9	118	I/O	5VT	Alternate: TIMER7_CH3, SDIO_D1, DCI_D3, CK_OUT1	
				Remap: TIMER2_CH3, I2C2_SDA	
				Default: PA8	
				Alternate: USART0_CK, TIMER0_CH0, CK_OUT0, VCORE,	
PA8	119	I/O	5VT	USBFS_SOF	
				Remap: TLI_R6, I2C2_SCL	
				Default: PA9	
PA9	120	I/O	5VT	Alternate: USART0_TX, TIMER0_CH1, USBFS_VBUS, DCI_D0	
				Remap: I2C2_SMBAI	
				Default: PA10	
PA10	121	I/O	5VT	Alternate: USART0_RX, TIMER0_CH2, USBFS_ID, DCI_D1	
				Default: PA11	
PA11	122	I/O	5VT	Alternate: USART0_CTS, CAN0_RX, USBFS_DM, TIMER0_CH3	
				Remap: TLI_R4	
				Default: PA12	
PA12	123	I/O	5VT	Alternate: USART0_RTS, USBFS_DP, CAN0_TX, TIMER0_ETI	
				Remap: TLI_R5	
D 4 4 0	401		<i></i>	Default: JTMS, SWDIO	
PA13	124	I/O	5VT	Remap: PA13	
NC	125			<u> </u>	
Vss_2	126	Р		Default: Vss_2	
V _{DD_2}	127	Р		Default: V _{DD_2}	
. 55_2		•		- 	





				GD32F207XX Datasileet	
Pin	Pins	Pin	I/O	Functions description	
Name		Type ⁽¹⁾	Level ⁽²⁾	i unotiono dosomption	
				Default: PH13	
PH13	128	I/O	5VT	Alternate: EXMC_D21	
				Remap: TLI_G2, TIMER7_CH0_ON, CAN0_TX	
				Default: PH14	
PH14	129	I/O	5VT	Alternate: EXMC_D22	
				Remap: TLI_G3, TIMER7_CH1_ON, DCI_D4	
				Default: PH15	
PH15	130	I/O	5VT	Alternate: EXMC_D23	
				Remap: TLI_G4, TIMER7_CH2_ON, DCI_D11	
				Default: PI0	
PI0	131	I/O	5VT	Alternate: EXMC_D24	
				Remap: TLI_G5, TIMER4_CH3, SPI1_NSS, I2S1_WS, DCI_D13	
				Default: PI1	
PI1	132	I/O	5VT	Alternate: EXMC_D25	
				Remap: TLI_G6, SPI1_SCK, I2S1_CK, DCI_D8	
				Default: PI2	
PI2	133	I/O	5VT	Alternate: EXMC_D26	
				Remap: TLI_G7, TIMER7_CH3, SPI1_MISO, DCI_D9	
				Default: PI3	
PI3	134	I/O	5VT	Alternate: EXMC_D27	
				Remap: TIMER7_ETI, SPI1_MOSI, I2S1_SD, TLI_R1, DCI_D10	
Vss	135	Р		Default: Vss	
V _{DD}	136	Р		Default: V _{DD}	
PA14	137	I/O	5VT	Default: JTCK, SWCLK	
	101	., 0		Remap: PA14	
				Default: JTDI	
PA15	138	I/O	5VT	Alternate: SPI2_NSS, I2S2_WS	
				Remap: TIMER1_CH0, TIMER1_ETI, PA15, SPI0_NSS	
				Default: PC10	
PC10	139	I/O	5VT	Alternate: UART3_TX, SDIO_D2, DCI_D8	
				Remap: USART2_TX, SPI2_SCK, I2S2_CK, TLI_R2	
				Default: PC11	
PC11	140	I/O	5VT	Alternate: UART3_RX, SDIO_D3, DCI_D4	
				Remap: USART2_RX, SPI2_MISO	
				Default: PC12	
PC12	141	I/O	5VT	Alternate: UART4_TX, SDIO_CK, DCI_D9	
				Remap: USART2_CK, SPI2_MOSI, I2S2_SD	
DD 0			5) (T	Default: PD0	
PD0	142	I/O	5VT	Alternate: EXMC_D2	
-				Remap: CAN0_RX, OSCIN	
DD4	440		5\ /T	Default: PD1	
PD1	143	I/O	5VT	Alternate: EXMC_D3	
-				Remap: CAN0_TX, OSCOUT	
PD2	144	I/O	5VT	Default: PD2	
	4		-·	Alternate: TIMER2_ETI, UART4_RX, SDIO_CMD, DCI_D11	
PD3	145	I/O	5VT	Default: PD3	





Pin		Pin	I/O	1	
Name	Pins		Level ⁽²⁾	Functions description	
Name		Type	Leven	All FVMO OLK	
				Alternate: EXMC_CLK	
				Remap: USART1_CTS, DCI_D5, TLI_G7, SPI1_SCK, I2S1_CK	
DD 4	4.40	1/0	5) /T	Default: PD4	
PD4	146	I/O	5VT	Alternate: EXMC_NOE	
				Remap: USART1_RTS	
DDs	4.47	1/0	5) /T	Default: PD5	
PD5	147	I/O	5VT	Alternate: EXMC_NWE	
,,	4.40	- 1		Remap: USART1_TX	
V _{SS_10}	148	P		Default: Vss_10	
V _{DD_10}	149	Р		Default: V _{DD_10}	
				Default: PD6	
PD6	150	I/O	5VT	Alternate: EXMC_NWAIT	
				Remap: USART1_RX, DCI_D10, TLI_B2, SPI2_MOSI, I2S2_SD	
				Default: PD7	
PD7	151	I/O	5VT	Alternate: EXMC_NE0, EXMC_NCE1	
				Remap: USART1_CK	
				Default: PG9	
PG9	152	I/O	5VT	Alternate: EXMC_NE1, EXMC_NCE2	
				Remap: DCI_VSYNC, USART5_RX	
				Default: PG10	
PG10	153	I/O	5VT	Alternate: EXMC_NCE3_0, EXMC_NE2	
				Remap: DCI_D2, TLI_G3, TLI_B2	
				Default: PG11	
PG11	154	I/O	5VT	Alternate: EXMC_NCE3_1	
				Remap: DCI_D3, TLI_B3, ENET_MII_TX_EN, ENET_RMII_TX_EN	
				Default: PG12	
PG12	155	I/O	5VT	Alternate: EXMC_NE3	
				Remap: USART5_RTS, TLI_B4, TLI_B1	
				Default: PG13	
PG13	156	I/O	5VT	Alternate: EXMC_A24	
				Remap: USART5_CTS, ENET_MII_TXD0, ENET_RMII_TXD0	
				Default: PG14	
PG14	157	I/O	5VT	Alternate: EXMC_A25	
				Remap: USART5_TX, ENET_MII_TXD1, ENET_RMII_TXD1	
Vss_11	158	Р		Default: Vss_10	
V _{DD_11}	159	Р		Default: V _{DD_10}	
				Default: PG15	
PG15	160	I/O	5VT	Alternate: EXMC_SDNCAS, USART5_CTS	
				Remap: DCI_D13	
				Default: JTDO	
PB3	161	I/O	5VT	Alternate:SPI2_SCK, I2S2_CK	
				Remap: PB3, TRACESWO, TIMER1_CH1, SPI0_SCK	
				Default: JNTRST	
PB4	162	I/O	5VT	Alternate: SPI2_MISO	
				Remap: TIMER2_CH0, PB4, SPI0_MISO	



			Ī	ODSZI ZUTAK Dalasileel	
Pin	Pins	Pin	I/O	Functions description	
Name	Pins	Type ⁽¹⁾	Level ⁽²⁾	runctions description	
				Default: PB5	
				Alternate: I2C0_SMBA, SPI2_MOSI, I2S2_SD, ENET_PPS_OUT,	
PB5	163	I/O		DCI_D10	
				Remap: TIMER2_CH1, SPI0_MOSI, CAN1_RX, EXMC_SDCKE1	
				Default: PB6	
PB6	164	I/O	5VT	Alternate: I2C0_SCL, TIMER3_CH0, DCI_D5	
1 50	104	1/0	3 7 1	Remap: USART0_TX, CAN1_TX, EXMC_SDNE1, SPI0_IO3	
				Default: PB7	
PB7	165	I/O	5VT	Alternate: I2C0_SDA , TIMER3_CH1, EXMC_NL, DCI_VSYNC	
FBI	103	1/0	301	Remap: USART0_RX, SPI0_IO4	
POOTO	166			•	
воото	100	I		Default: BOOT0	
				Default: PB8	
PB8	167	I/O	5VT	Alternate: TIMER3_CH2, TIMER9_CH0, ENET_MII_TXD3,	
				SDIO_D4, DCI_D6	
				Remap: I2C0_SCL, CAN0_RX, TLI_B6	
				Default: PB9	
PB9	168	I/O	5VT	Alternate: TIMER3_CH3, TIMER10_CH0, SDIO_D5, DCI_D7	
				Remap: I2C0_SDA, CAN0_TX, TLI_B7, SPI1_NSS, I2S1_WS	
			5VT	Default: PE0	
PE0	169	I/O		Alternate: TIMER3_ETI, EXMC_NBL0, UART7_RX	
				Remap: DCI_D2	
				Default: PE1	
PE1	170	I/O	5VT	Alternate: EXMC_NBL1, UART7_TX	
				Remap: DCI_D3	
Vss_3	171	Р		Default: Vss_3	
V _{DD_3}	172	Р		Default: V _{DD_3}	
				Default: PI4	
PI4	173	I/O	5VT	Alternate: EXMC_NBL2	
				Remap: TLI_B4, TIMER7_BRKIN, DCI_D5	
				Default: PI5	
PI5	174	I/O	5VT	Alternate: EXMC_NBL3	
				Remap: TLI_B5, TIMER7_CH0, DCI_VSYNC	
				Default: PI6	
PI6	175	I/O	5VT	Alternate: EXMC_D28	
		•		Remap: TLI_B6, TIMER7_CH1, DCI_D6	
				Default: PI7	
PI7	176	I/O	5VT	Alternate: EXMC_D29	
'''		., 0		Remap: TLI_B7, TIMER7_CH2, DCI_D7	
			l	1.0map. 1=1_D1, 11WE1(1_0112, D01_D1	

Notes:

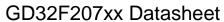
- (1) Type: I = input, O = output, P = power.
- (2) I/O Level: 5VT = 5 V tolerant.



2.6.2. GD32F207Zx LQFP144 pin definitions

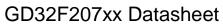
Table 2-4. GD32F207Zx LQFP144 pin definitions

Pin Name	Pins	Pin Type ⁽¹⁾	I/O Level ⁽²⁾	Functions description
				Default: PE2
PE2	1	I/O	5VT	Alternate: TRACECK, EXMC_A23
				Remap: ENET_MII_TXD3
PE3	2	I/O	5VT	Default: PE3
PES		1/0	371	Alternate: TRACED0, EXMC_A19
				Default: PE4
PE4	3	I/O	5VT	Alternate:TRACED1, EXMC_A20
				Remap: DCI_D4, TLI_B0
				Default: PE5
PE5	4	I/O	5VT	Alternate:TRACED2, EXMC_A21
				Remap: TIMER8_CH0, DCI_D6, TLI_G0
DE 0	_		=\ /=	Default: PE6
PE6	5	I/O	5VT	Alternate:TRACED3, EXMC_A22
	_	_		Remap: TIMER8_CH1, DCI_D7, TLI_G1
V _{BAT}	6	Р		Default: V _{BAT}
PC13-				Default: PC13
TAMPER-	7	I/O	5VT	Alternate: TAMPER-RTC
RTC				
PC14-	8	I/O		Default: PC14
OSC32IN	Ü	1/0		Alternate: OSC32IN
PC15-	9	I/O		Default: PC15
OSC32OUT	Э	1/0		Alternate: OSC32OUT
				Default: PF0
PF0	10	I/O	5VT	Alternate: EXMC_A0
				Remap: I2C1_SDA
				Default: PF1
PF1	11	I/O	5VT	Alternate: EXMC_A1
				Remap: I2C1_SCL
				Default: PF2
PF2	12	I/O	5VT	Alternate: EXMC_A2
				Remap: I2C1_SMBA
PF3	13	I/O	5VT	Default: PF3
	-			Alternate: EXMC_A3, ADC2_IN9
PF4	14	I/O	5VT	Default: PF4
				Alternate: EXMC_A4, ADC2_IN14
PF5	15	I/O	5VT	Default: PF5
-	1.5			Alternate: EXMC_A5, ADC2_IN15
Vss_5	16	P		Default: Vss_5
V_{DD_5}	17	Р		Default: V _{DD_5}
PF6	18	I/O		Default: PF6
				Alternate: ADC2_IN4, EXMC_NIORD



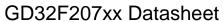


				GD32F207XX DataSilee
Pin Name	Pins	Pin	I/O	Functions description
Pili Naille	FIIIS	Type ⁽¹⁾	Level ⁽²⁾	Functions description
				Remap: TIMER9_CH0, UART6_RX
				Default: PF7
PF7	19	I/O		Alternate: ADC2_IN5, EXMC_NREG
				Remap: TIMER10_CH0, UART6_TX
				Default: PF8
PF8	20	I/O		Alternate: ADC2_IN6, EXMC_NIOWR
				Remap: TIMER12_CH0
				Default: PF9
PF9	21	I/O		Alternate: ADC2_IN7, EXMC_CD
				Remap: TIMER13_CH0
				Default: PF10
PF10	22	I/O		Alternate: ADC2_IN8, EXMC_INTR
				Remap: DCI_D11, TLI_DE
OSCIN	23	1		Default: OSCIN
OSCIIV	23	'		Remap: PD0, PH0
OSCOUT	24	0		Default: OSCOUT
030001	24	U		Remap: PD1, PH1
NRST	25	I/O		Default: NRST
				Default: PC0
PC0	26	I/O	I/O	Alternate: ADC012_IN10
				Remap: EXMC_SDNWE
PC1	27	I/O		Default: PC1
PCI	21	1/0		Alternate: ADC012_IN11, ENET_MDC
				Default: PC2
PC2	28	I/O		Alternate: ADC012_IN12, ENET_MII_TXD2
				Remap: EXMC_SDNE0, SPI1_MISO
				Default: PC3
PC3	29	I/O		Alternate: ADC012_IN13, ENET_MII_TX_CLK
				Remap: EXMC_SDCKE0, SPI1_MOSI, I2S1_SD
V _{SSA}	30	Р		Default: V _{SSA}
V _{REF} -	31	Р		Default: V _{REF} -
V _{REF+}	32	Р		Default: V _{REF+}
V_{DDA}	33	Р		Default: V _{DDA}
				Default: PA0
				Alternate: WKUP, USART1_CTS, ADC012_IN0,
PA0-WKUP	34	I/O		TIMER1_CH0, TIMER1_ETI, TIMER4_CH0, TIMER7_ETI,
				ENET_MII_CRS
				Remap: UART3_TX
				Default: PA1
D 4	25	1/0		Alternate: USART1_RTS, ADC012_IN1, TIMER1_CH1,
PA1	35	I/O		TIMER4_CH1,ENET_MII_RX_CLK, ENET_RMII_REF_CLK
				Remap: UART3_RX
				Default: PA2
PA2	36	I/O		Alternate: USART1_TX, ADC012_IN2, TIMER1_CH2,
				TIMER4_CH2, TIMER8_CH0, ENET_MDIO, SPI0_IO3



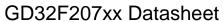


					GD32F207XX DataSileet	
	Pin Name	Pins	Pin	I/O	Functions description	
	riii Naiile	FIIIS	Type ⁽¹⁾	Level ⁽²⁾	Functions description	
					Default: PA3	
	DAG	07	1/0		Alternate: USART1_RX, ADC012_IN3, TIMER1_CH3,	
	PA3	37	I/O		TIMER4_CH3, TIMER8_CH1, ENET_MII_COL, SPI0_IO4	
					Remap: TLI_B5	
	V_{SS_4}	38	Р		Default: V _{SS_4}	
	V_{DD_4}	39	Р		Default: V _{DD_4}	
İ					Default: PA4	
	54.4	4.0			Alternate: SPI0_NSS, USART1_CK, DAC_OUT0,	
	PA4	40	I/O		ADC01_IN4, DCI_HSYNC	
					Remap: SPI2_NSS, I2S2_WS, TLI_VSYNC	
					Default: PA5	
	PA5	41	I/O		Alternate: SPI0_SCK, ADC01_IN5, DAC_OUT1	
					Remap: TIMER1_CH0, TIMER1_ETI, TIMER7_CH0_ON	
					Default: PA6	
	PA6	42	I/O		Alternate: SPI0_MISO, ADC01_IN6, TIMER2_CH0,	
	PAO	42	1/0		TIMER7_BRKIN, TIMER12_CH0, DCI_PIXCLK	
					Remap: TIMER0_BRKIN, TLI_G2	
					Default: PA7	
					Alternate: SPI0_MOSI, ADC01_IN7, TIMER2_CH1,	
	PA7	43	I/O		TIMER7_CH0_ON, TIMER13_CH0, ENET_MII_RX_DV,	
					ENET_RMII_CRS_DV	
					Remap: TIMER0_CH0_ON	
					Default: PC4	
	PC4	44	I/O		Alternate: ADC01_IN14, ENET_MII_RXD0.	
					ENET_RMII_RXD0	
					Default: PC5	
	PC5	45	I/O		Alternate: ADC01_IN15, ENET_MII_RXD1,	
					ENET_RMII_RXD1	
					Default: PB0	
	PB0	46	I/O		Alternate: ADC01_IN8, TIMER2_CH2, TIMER7_CH1_ON,	
					ENET_MII_RXD2	
					Remap: TIMER0_CH1_ON, TLI_R3	
					Default: PB1	
	PB1	47	I/O		Alternate: ADC01_IN9, TIMER2_CH3, TIMER7_CH2_ON,	
					ENET_MII_RXD3 Remap: TIMER0_CH2_ON, TLI_R6	
ŀ	DDO	40	1/0	C)/T	•	
	PB2	48	I/O	5VT	Default: PB2, BOOT1	
	PF11	49	I/O	5VT	Default: PF11	
					Alternate: EXMC_NIOS16, DCI_D12, EXMC_SDNRAS	
	PF12	50	I/O	5VT	Default: PF12 Alternate: EXMC_A6	
ł	\/o- ·	51	P			
ļ	V _{SS_6}	51			Default: Vss_6	
ŀ	V _{DD_6}	52	Р		Default: V _{DD_6}	
	PF13	53	I/O	5VT	Default: PF13	
						Alternate: EXMC_A7



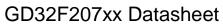


					GD32F207XX Datasneet
	Pin Name	Pins	Pin Type ⁽¹⁾	I/O Level ⁽²⁾	Functions description
					Default: PF14
	PF14	54	I/O	5VT	Alternate: EXMC A8
					Default: PF15
	PF15	55	I/O	5VT	Alternate: EXMC_A9
					Default: PG0
	PG0	56	I/O	5VT	Alternate: EXMC_A10
					Default: PG1
	PG1	57	I/O	5VT	Alternate: EXMC_A11
					Default: PE7
	PE7	58	I/O	5VT	Alternate: EXMC_D4, UART6_RX
					Remap: TIMER0_ETI
					Default: PE8
	PE8	59	I/O	5VT	Alternate: EXMC_D5, UART6_TX
					Remap: TIMER0_CH0_ON
					Default: PE9
	PE9	60	I/O	5VT	Alternate: EXMC_D6
					Remap: TIMER0_CH0
	Vss_7	61	Р		Default: Vss_7
İ	V _{DD_7}	62	Р		Default: V _{DD_7}
İ					Default: PE10
	PE10	63	I/O	5VT	Alternate: EXMC_D7
					Remap: TIMER0_CH1_ON
=		64	I/O	5VT	Default: PE11
	PE11				Alternate: EXMC_D8
					Remap: TIMER0_CH1, TLI_G3
		65	I/O	5VT	Default: PE12
	PE12				Alternate: EXMC_D9
					Remap: TIMER0_CH2_ON, TLI_B4
					Default: PE13
	PE13	66	I/O	5VT	Alternate: EXMC_D10
					Remap: TIMER0_CH2, TLI_DE
					Default: PE14
	PE14	67	I/O	5VT	Alternate: EXMC_D11
					Remap: TIMER0_CH3, TLI_ PIXCLK
					Default: PE15
	PE15	68	I/O	5VT	Alternate: EXMC_D12
					Remap: TIMER0_BRKIN, TLI_R7
					Default: PB10
	PB10	69	I/O	5VT	Alternate: I2C1_SCL, USART2_TX, ENET_MII_RX_ER
					Remap: TIMER1_CH2, TLI_G4, SPI1_SCK, I2S1_CK
		70	I/O	5VT	Default: PB11
	PB11				Alternate: I2C1_SDA, USART2_RX, ENET_MII_TX_EN,
	ווטו				ENET_RMII_TX_EN
					Remap: TIMER1_CH3, TLI_G5
	V_{SS_1}	71	Р		Default: V _{SS_1}



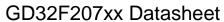


				GD32F207xx Datasheet
Pin Name	Pins	Pin	I/O	Functions description
1 III Name	1 1113	Type ⁽¹⁾	Level ⁽²⁾	Tunotions description
V_{DD_1}	72	Р		Default: V _{DD_1}
				Default: PB12
DD40	70	I/O	EV/T	Alternate: SPI1_NSS, I2C1_SMBA, USART2_CK,
PB12	73		5VT	TIMER0_BRKIN, I2S1_WS, CAN1_RX, ENET_MII_TXD0,
				ENET_RMII_TXD0
				Default: PB13
PB13	74	I/O	5VT	Alternate: SPI1_SCK, USART2_CTS, TIMER0_CH0_ON,
				I2S1_CK, CAN1_TX , ENET_MII_TXD1, ENET_RMII_TXD1
				Default: PB14
PB14	75	I/O	5VT	Alternate: SPI1_MISO, USART2_RTS, TIMER0_CH1_ON,
				TIMER11_CH0
				Default: PB15
PB15	76	I/O	5VT	Alternate: SPI1_MOSI, TIMER0_CH2_ON, I2S1_SD,
				TIMER11_CH1
			5VT	Default: PD8
PD8	77	I/O		Alternate: EXMC_D13
				Remap: USART2_TX, ENET_MII_RX_DV,
				ENET_RMII_CRS_DV
DDO	78	I/O	5VT	Default: PD9
PD9				Alternate: EXMC_D14 Remap: USART2_RX, ENET_MII_RXD0, ENET_RMII_RXD0
			I/O 5VT Default: PD10 Alternate: EXMC_D15 Remap: USART2_CK, ENET_MII_RXD0, EN ENET_RMII_RXD1, TLI_B3	<u> </u>
	79	I/O		
PD10				_
	80	I/O	5VT	Default: PD11
PD11				Alternate: EXMC_A16
				Remap: USART2_CTS, ENET_MII_RXD2
		I/O	5VT	Default: PD12
PD12	81			Alternate: EXMC_A17
				Remap: TIMER3_CH0, USART2_RTS
	82	I/O	5VT	Default: PD13
PD13				Alternate: EXMC_A18
				Remap: TIMER3_CH1
V _{SS_8}	83	Р		Default: Vss_8
V _{DD_8}	84	Р		Default: V _{DD_8}
	85	I/O	5VT	Default: PD14
PD14				Alternate: EXMC_D0
				Remap: TIMER3_CH2
	86	I/O	5VT	Default: PD15
PD15				Alternate: EXMC_D1
				Remap: TIMER3_CH3
PG2	87	I/O	5VT	Default: PG2
. 02	"	., 0	341	Alternate: EXMC_A12
PG3	88	I/O	5VT	Default: PG3
				Alternate: EXMC_A13



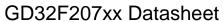


					GD32F207XX DataSHeet
	Pin Name	Pins	Pin	I/O	Functions description
	riii Naiile	FIIIS	Type ⁽¹⁾	Level ⁽²⁾	Functions description
Ī	DC4	89	I/O	5VT	Default: PG4
	PG4	09	1/0	5 / 1	Alternate: EXMC_A14, EXMC_BA0
	PG5	90	I/O	5VT	Default: PG5
	F G 5	90	1/0	5 / 1	Alternate: EXMC_A15, EXMC_BA1
	PG6	91	I/O	5VT	Default: PG6
					Alternate: EXMC_INT1
ļ					Remap: DCI_D12, TLI_R7
	PG7	92	I/O	5VT	Default: PG7
					Alternate: EXMC_INT2, DCI_D13
ŀ					Remap: USART5_CK, TLI_ PIXCLK
					Default: PG8
	PG8	93	I/O	5VT	Alternate: EXMC_SDCLK, USART5_RTS
-					Remap: ENET_PPS_OUT
-	Vss_9	94	Р		Default: Vss_9
-	V_{DD_9}	95	Р		Default: V _{DD_9}
					Default: PC6
	PC6	96	I/O	5VT	Alternate: I2S1_MCK, TIMER7_CH0, SDIO_D6,
			"		USART5_TX
ŀ					Remap: TIMER2_CH0, DCI_D0, TLI_HSYNC
					Default: PC7
	PC7	97	I/O	5VT	Alternate: I2S2_MCK, TIMER7_CH1, SDIO_D7,
					USART5_RX
ŀ					Remap: TIMER2_CH1, DCI_D1, TLI_G6 Default: PC8
	PC8	00	I/O	5VT	Alternate: TIMER7_CH2, SDIO_D0, DCI_D2, USART5_CK
		98			Remap: TIMER2_CH2
ŀ					Default: PC9
	PC9	99	I/O	5VT	Alternate: TIMER7_CH3, SDIO_D1, DCI_D3, CK_OUT1
	1 00				Remap: TIMER2_CH3, I2C2_SDA
ŀ					Default: PA8
		100	I/O	5VT	Alternate: USART0_CK, TIMER0_CH0, CK_OUT0, VCORE,
	PA8				USBFS_SOF
					Remap: TLI_R6, I2C2_SCL
ŀ					Default: PA9
		101	I/O	5VT	Alternate: USART0_TX, TIMER0_CH1, USBFS_VBUS,
	PA9				DCI_D0
					Remap: I2C2_SMBAI
	DA40	400	1/0	E) /T	Default: PA10
	PA10	102	I/O	5VT	Alternate: USART0_RX, TIMER0_CH2, USBFS_ID, DCI_D1
		103	I/O	5VT	Default: PA11
	DA11				Alternate: USART0_CTS, CAN0_RX, USBFS_DM,
	PA11				TIMER0_CH3
ļ					Remap: TLI_R4
					Default: PA12
	PA12	104	I/O	5VT	Alternate: USART0_RTS, USBFS_DP, CAN0_TX,
					TIMER0_ETI





		Pin	I/O	
Pin Name	Pins			Functions description
		Type ⁽¹⁾	Level ⁽²⁾	
				Remap: TLI_R5
PA13	105	I/O	5VT	Default: JTMS, SWDIO
				Remap: PA13
NC	106			-
V _{SS_2}	107	Р		Default: V _{SS_2}
V _{DD_2}	108	Р		Default: V _{DD_2}
PA14	109	I/O	5VT	Default: JTCK, SWCLK
		., 0		Remap: PA14
				Default: JTDI
PA15	110	I/O	5VT	Alternate: SPI2_NSS, I2S2_WS
				Remap: TIMER1_CH0, TIMER1_ETI, PA15, SPI0_NSS
				Default: PC10
PC10	111	I/O	5VT	Alternate: UART3_TX, SDIO_D2, DCI_D8
				Remap: USART2_TX, SPI2_SCK, I2S2_CK, TLI_R2
				Default: PC11
PC11	112	I/O	5VT	Alternate: UART3_RX, SDIO_D3, DCI_D4
				Remap: USART2_RX, SPI2_MISO
				Default: PC12
PC12	113	I/O	5VT	Alternate: UART4_TX, SDIO_CK, DCI_D9
				Remap: USART2_CK, SPI2_MOSI, I2S2_SD
		Default: PD0 I/O 5VT Alternate: EXMC_D2		
PD0	114		5VT	
				Remap: CANO_RX, OSCIN
DD4	445	1/0	5) /T	Default: PD1
PD1	115	I/O	5VT	Alternate: EXMC_D3
				Remap: CAN0_TX, OSCOUT
PD2	116	I/O	5VT	Default: PD2 Alternate: TIMER2_ETI, UART4_RX, SDIO_CMD, DCI_D11
				Default: PD3
				Alternate: EXMC CLK
PD3	117	I/O	5VT	Remap: USART1_CTS, DCI_D5, TLI_G7, SPI1_SCK,
				I2S1_CK
				Default: PD4
PD4	118	I/O	5VT	Alternate: EXMC_NOE
		","		Remap: USART1_RTS
				Default: PD5
PD5	119	I/O	5VT	Alternate: EXMC_NWE
. 23		., C		Remap: USART1_TX
Vss_10	120	Р		Default: Vss_10
V _{DD_10}	121	P		Default: V _{DD_10}
* DD_10		•		Default: PD6
	122	I/O	5VT	Alternate: EXMC_NWAIT
PD6				Remap: USART1_RX, DCI_D10, TLI_B2, SPI2_MOSI,
				I2S2_SD
PD7	123	I/O	5VT	Default: PD7
101	123	1/0	J V I	Dordan. 1 D1





		5 ;		GD32F207XX DataStiee
Pin Name	Pins	Pin	1/0	Functions description
		Type ⁽¹⁾	Level ⁽²⁾	
				Alternate: EXMC_NE0, EXMC_NCE1
				Remap: USART1_CK
				Default: PG9
PG9	124	I/O	5VT	Alternate: EXMC_NE1, EXMC_NCE2
				Remap: DCI_VSYNC, USART5_RX
				Default: PG10
PG10	125	I/O	5VT	Alternate: EXMC_NCE3_0, EXMC_NE2
				Remap: DCI_D2, TLI_G3, TLI_B2
				Default: PG11
PG11	126	I/O	5VT	Alternate: EXMC_NCE3_1
				Remap: DCI_D3, TLI_B3, ENET_MII_TX_EN,
				ENET_RMII_TX_EN
DC12	107	1/0	E\/T	Default: PG12
PG12	127	I/O	5VT	Alternate: EXMC_NE3 Remap: USART5_RTS, TLI_B4, TLI_B1
				Default: PG13
				Alternate: EXMC_A24
PG13	128	I/O	5VT	Remap: USART5_CTS, ENET_MII_TXD0,
				ENET_RMII_TXD0
				Default: PG14
PG14	129	I/O	5VT	Alternate: EXMC_A25
1014	123	1/0	3 7 1	Remap: USART5_TX, ENET_MII_TXD1, ENET_RMII_TXD1
V _{SS_11}	130	Р		Default: Vss 10
V _{DD_11}	131	Р		Default: V _{DD} 10
133_11		-		Default: PG15
PG15	132	I/O	5VT	Alternate: EXMC_SDNCAS, USART5_CTS
		., C		Remap: DCI_D13
				Default: JTDO
PB3	133	I/O	5VT	Alternate:SPI2_SCK, I2S2_CK
		","		Remap: PB3, TRACESWO, TIMER1_CH1, SPI0_SCK
				Default: JNTRST
PB4	134	I/O	5VT	Alternate: SPI2_MISO
				Remap: TIMER2_CH0, PB4, SPI0_MISO
				Default: PB5
				Alternate: I2C0_SMBA, SPI2_MOSI, I2S2_SD,
PB5	135	I/O		ENET_PPS_OUT, DCI_D10
				Remap: TIMER2_CH1, SPI0_MOSI, CAN1_RX,
				EXMC_SDCKE1
				Default: PB6
PB6	136	I/O	5VT	Alternate: I2C0_SCL, TIMER3_CH0, DCI_D5
				Remap: USART0_TX, CAN1_TX, EXMC_SDNE1, SPI0_IO3
				Default: PB7
PB7	137	I/O	5VT	Alternate: I2C0_SDA , TIMER3_CH1, EXMC_NL,
	.57	., 0	571	DCI_VSYNC
				Remap: USART0_RX, SPI0_IO4
BOOT0	138	I		Default: BOOT0



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Pin Name	Pins	Pin Type ⁽¹⁾	I/O Level ⁽²⁾	Functions description
PB8	139	I/O	5VT	Default: PB8 Alternate: TIMER3_CH2, TIMER9_CH0, ENET_MII_TXD3, SDIO_D4, DCI_D6 Remap: I2C0_SCL, CAN0_RX, TLI_B6
PB9	140	I/O	5VT	Default: PB9 Alternate: TIMER3_CH3, TIMER10_CH0, SDIO_D5, DCI_D7 Remap: I2C0_SDA, CAN0_TX, TLI_B7, SPI1_NSS, I2S1_WS
PE0	141	I/O	5VT	Default: PE0 Alternate: TIMER3_ETI, EXMC_NBL0, UART7_RX Remap: DCI_D2
PE1	142	I/O		Default: PE1 Alternate: EXMC_NBL1, UART7_TX Remap: DCI_D3
V _{SS_3}	143	Р		Default: V _{SS_3}
V _{DD_3}	144	Р		Default: V _{DD_3}

Notes:

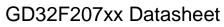
- (1) Type: I = input, O = output, P = power.
- (2) I/O Level: 5VT = 5 V tolerant.



2.6.3. GD32F207Vx LQFP100 pin definitions

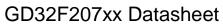
Table 2-5. GD32F207Vx LQFP100 pin definitions

		Pin	I/O	pin definitions
Pin Name	Pins	Type ⁽¹⁾	Level ⁽²⁾	Functions description
		71		Default: PE2
PE2	1	I/O	5VT	Alternate: TRACECK, EXMC_A23
				Remap: ENET_MII_TXD3
BE0	•	1/0	5) (T	Default: PE3
PE3	2	I/O	5VT	Alternate: TRACED0, EXMC_A19
				Default: PE4
PE4	3	I/O	5VT	Alternate:TRACED1, EXMC_A20
				Remap: DCI_D4, TLI_B0
				Default: PE5
PE5	4	I/O	5VT	Alternate:TRACED2, EXMC_A21
				Remap: TIMER8_CH0, DCI_D6, TLI_G0
				Default: PE6
PE6	5	I/O	5VT	Alternate:TRACED3, EXMC_A22
				Remap: TIMER8_CH1, DCI_D7, TLI_G1
V _{BAT}	6	Р		Default: V _{BAT}
PC13-				Default: PC13
TAMPER-	7	I/O	5VT	Alternate: TAMPER-RTC
RTC				7 III O III O III O III O II O II O II
PC14-	0	I/O		Default: PC14
OSC32IN	OSC32IN 8 I/O	1/0		Alternate: OSC32IN
PC15-	9	I/O		Default: PC15
OSC32OUT	9	1/0		Alternate: OSC32OUT
V _{SS_5}	10	Р		Default: Vss_5
V_{DD_5}	11	Р		Default: V _{DD_5}
OCCINI	10			Default: OSCIN
OSCIN	12	ı		Remap: PD0, PH0
OSCOUT	13	0		Default: OSCOUT
000001	13			Remap: PD1, PH1
NRST	14	I/O		Default: NRST
				Default: PC0
PC0	15	I/O		Alternate: ADC012_IN10
				Remap: EXMC_SDNWE
PC1	16	I/O		Default: PC1
		., 0		Alternate: ADC012_IN11, ENET_MDC
				Default: PC2
PC2	17	I/O		Alternate: ADC012_IN12, ENET_MII_TXD2
				Remap: EXMC_SDNE0, SPI1_MISO
Bos	4.5			Default: PC3
PC3	18	I/O		Alternate: ADC012_IN13, ENET_MII_TX_CLK
.,,	4.5			Remap: EXMC_SDCKE0, SPI1_MOSI, I2S1_SD
Vssa	19	Р		Default: V _{SSA}



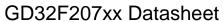


				GD32F207XX DataSileet
Pin Name	Pins	Pin	I/O	Functions description
		Type ⁽¹⁾	Level ⁽²⁾	
V _{REF} -	20	Р		Default: V _{REF} .
V _{REF+}	21	Р		Default: V _{REF+}
V _{DDA}	22	Р		Default: V _{DDA}
				Default: PA0
				Alternate: WKUP, USART1_CTS, ADC012_IN0,
PA0-WKUP	23	I/O		TIMER1_CH0, TIMER1_ETI, TIMER4_CH0, TIMER7_ETI,
				ENET_MII_CRS
				Remap: UART3_TX
				Default: PA1
PA1	24	I/O		Alternate: USART1_RTS, ADC012_IN1, TIMER1_CH1,
','.		., 0		TIMER4_CH1,ENET_MII_RX_CLK, ENET_RMII_REF_CLK
				Remap: UART3_RX
				Default: PA2
PA2	25	I/O		Alternate: USART1_TX, ADC012_IN2, TIMER1_CH2,
				TIMER4_CH2, TIMER8_CH0, ENET_MDIO, SPI0_IO3
				Default: PA3
PA3	26	I/O		Alternate: USART1_RX, ADC012_IN3, TIMER1_CH3,
				TIMER4_CH3, TIMER8_CH1, ENET_MII_COL, SPI0_IO4
				Remap: TLI_B5
V _{SS_4}	27	Р		Default: V _{SS_4}
V _{DD_4}	28	Р		Default: V _{DD_4}
				Default: PA4
PA4	29	I/O		Alternate: SPI0_NSS, USART1_CK, DAC_OUT0,
		1/0		ADC01_IN4, DCI_HSYNC
				Remap: SPI2_NSS, I2S2_WS, TLI_VSYNC
				Default: PA5
PA5	30	I/O		Alternate: SPI0_SCK, ADC01_IN5, DAC_OUT1
				Remap: TIMER1_CH0, TIMER1_ETI, TIMER7_CH0_ON
				Default: PA6
PA6	31	I/O		Alternate: SPI0_MISO, ADC01_IN6, TIMER2_CH0,
				TIMER7_BRKIN, TIMER12_CH0, DCI_PIXCLK
				Remap: TIMER0_BRKIN, TLI_G2
				Default: PA7
DA7	22	1/0		Alternate: SPI0_MOSI, ADC01_IN7, TIMER2_CH1,
PA7	32	I/O		TIMER7_CH0_ON, TIMER13_CH0, ENET_MII_RX_DV, ENET_RMII_CRS_DV
				Remap: TIMER0_CH0_ON
				Default: PC4
PC4	33	I/O		Alternate: ADC01_IN14, ENET_MII_RXD0.
104	104 33	","		ENET_RMII_RXD0
				Default: PC5
PC5	34	I/O		Alternate: ADC01_IN15, ENET_MII_RXD1,
				ENET_RMII_RXD1
				Default: PB0
PB0	35	I/O		Alternate: ADC01_IN8, TIMER2_CH2, TIMER7_CH1_ON,



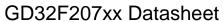


				GD32F207XX DataSileet
Pin Name	Pins	Pin	I/O	Functions description
- III Nullio	1 1110	Type ⁽¹⁾	Level ⁽²⁾	T difference decempation
				ENET_MII_RXD2
				Remap: TIMER0_CH1_ON, TLI_R3
				Default: PB1
PB1	36	I/O		Alternate: ADC01_IN9, TIMER2_CH3, TIMER7_CH2_ON,
PDI	30	1/0		ENET_MII_RXD3
				Remap: TIMER0_CH2_ON, TLI_R6
PB2	37	I/O	5VT	Default: PB2, BOOT1
				Default: PE7
PE7	38	I/O	5VT	Alternate: EXMC_D4, UART6_RX
				Remap: TIMER0_ETI
				Default: PE8
PE8	39	I/O	5VT	Alternate: EXMC_D5, UART6_TX
				Remap: TIMER0_CH0_ON
				Default: PE9
PE9	40	I/O	5VT	Alternate: EXMC_D6
				Remap: TIMER0_CH0
				Default: PE10
PE10	41	I/O	5VT	Alternate: EXMC_D7
				Remap: TIMER0_CH1_ON
				Default: PE11
PE11	42	I/O	5VT	Alternate: EXMC_D8
				Remap: TIMER0_CH1, TLI_G3
				Default: PE12
PE12	43	I/O	5VT	Alternate: EXMC_D9
				Remap: TIMER0_CH2_ON, TLI_B4
				Default: PE13
PE13	44	I/O	5VT	Alternate: EXMC_D10
				Remap: TIMER0_CH2, TLI_DE
				Default: PE14
PE14	45	I/O	5VT	Alternate: EXMC_D11
				Remap: TIMER0_CH3, TLI_ PIXCLK
				Default: PE15
PE15	46	I/O	5VT	Alternate: EXMC_D12
				Remap: TIMER0_BRKIN, TLI_R7
				Default: PB10
PB10	47	I/O	5VT	Alternate: I2C1_SCL, USART2_TX, ENET_MII_RX_ER
				Remap: TIMER1_CH2, TLI_G4, SPI1_SCK, I2S1_CK
				Default: PB11
DD44	40	1/0	5) /T	Alternate: I2C1_SDA, USART2_RX, ENET_MII_TX_EN,
PB11	48	I/O	5VT	ENET_RMII_TX_EN
	<u> </u>			Remap: TIMER1_CH3, TLI_G5
Vss_1	49	Р		Default: Vss_1
V_{DD_1}	50	Р		Default: V _{DD_1}
				Default: PB12
PB12	51	I/O	5VT	Alternate: SPI1_NSS, I2C1_SMBA, USART2_CK,
				TIMERO_BRKIN, I2S1_WS, CAN1_RX, ENET_MII_TXD0,



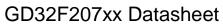


					GD32F207XX Datasneet
	Pin Name	Pins	Pin	I/O	Functions description
	1 III I I I I I I		Type ⁽¹⁾	Level ⁽²⁾	i anotiono accomption
					ENET_RMII_TXD0
					Default: PB13
	PB13	52	I/O	5VT	Alternate: SPI1_SCK, USART2_CTS, TIMER0_CH0_ON,
					I2S1_CK, CAN1_TX , ENET_MII_TXD1, ENET_RMII_TXD1
					Default: PB14
	PB14	53	I/O	5VT	Alternate: SPI1_MISO, USART2_RTS, TIMER0_CH1_ON,
					TIMER11_CH0
					Default: PB15
	PB15	54	I/O	5VT	Alternate: SPI1_MOSI, TIMER0_CH2_ON, I2S1_SD,
					TIMER11_CH1
					Default: PD8
	PD8	55	I/O	5VT	Alternate: EXMC_D13
	PDO	55	1/0	301	Remap: USART2_TX, ENET_MII_RX_DV,
					ENET_RMII_CRS_DV
					Default: PD9
	PD9	56	I/O	5VT	Alternate: EXMC_D14
					Remap: USART2_RX, ENET_MII_RXD0, ENET_RMII_RXD0
					Default: PD10
	PD10	57	I/O	5VT	Alternate: EXMC_D15
	1 010	31	1/0	501	Remap: USART2_CK, ENET_MII_RXD1,
ļ					ENET_RMII_RXD1, TLI_B3
			58 I/O 5		Default: PD11
	PD11	58		5VT	Alternate: EXMC_A16
ļ					Remap: USART2_CTS, ENET_MII_RXD2
					Default: PD12
	PD12	59	I/O	5VT	Alternate: EXMC_A17
ļ					Remap: TIMER3_CH0, USART2_RTS
					Default: PD13
	PD13	60	I/O	5VT	Alternate: EXMC_A18
					Remap: TIMER3_CH1
					Default: PD14
	PD14	61	I/O	5VT	Alternate: EXMC_D0
ļ					Remap: TIMER3_CH2
					Default: PD15
	PD15	62	I/O	5VT	Alternate: EXMC_D1
ļ					Remap: TIMER3_CH3
					Default: PC6
	PC6	63	I/O	5VT	Alternate: I2S1_MCK, TIMER7_CH0, SDIO_D6,
					USART5_TX
ļ					Remap: TIMER2_CH0, DCI_D0, TLI_HSYNC
					Default: PC7
	PC7	64	I/O	5VT	Alternate: I2S2_MCK, TIMER7_CH1, SDIO_D7,
					USART5_RX
-					Remap: TIMER2_CH1, DCI_D1, TLI_G6
	PC8	65	I/O	5VT	Default: PC8
					Alternate: TIMER7_CH2, SDIO_D0, DCI_D2, USART5_CK





					GD32F207XX Datasneet
	Pin Name	Pins	Pin	1/0	Functions description
			Type ⁽¹⁾	Level ⁽²⁾	·
-					Remap: TIMER2_CH2
					Default: PC9
	PC9	66	I/O	5VT	Alternate: TIMER7_CH3, SDIO_D1, DCI_D3, CK_OUT1
-					Remap: TIMER2_CH3, I2C2_SDA
					Default: PA8
	PA8	67	I/O	5VT	Alternate: USART0_CK, TIMER0_CH0, CK_OUT0, VCORE,
					USBFS_SOF
ŀ					Remap: TLI_R6, I2C2_SCL Default: PA9
	PA9	68	I/O	5VT	Alternate: USART0_TX, TIMER0_CH1, USBFS_VBUS, DCI_D0
					Remap: I2C2_SMBAI
-					Default: PA10
	PA10	69	I/O	5VT	Alternate: USART0_RX, TIMER0_CH2, USBFS_ID, DCI_D1
-					Default: PA11
					Alternate: USARTO_CTS, CANO_RX, USBFS_DM,
	PA11	70	I/O	5VT	TIMER0_CH3
					Remap: TLI_R4
					Default: PA12
	DA 40	74	1/0		Alternate: USART0_RTS, USBFS_DP, CAN0_TX,
	PA12	71	I/O	5VT	TIMER0_ETI
					Remap: TLI_R5
	PA13	72	I/O	5VT	Default: JTMS, SWDIO
	FAIS	12	1/0	371	Remap: PA13
	NC	73			-
	Vss_2	74	Р		Default: Vss_2
	V_{DD_2}	75	Р		Default: V _{DD_2}
	PA14	76	I/O	5VT	Default: JTCK, SWCLK
	FA14	70	1/0	371	Remap: PA14
					Default: JTDI
	PA15	77	I/O	5VT	Alternate: SPI2_NSS, I2S2_WS
ļ					Remap: TIMER1_CH0, TIMER1_ETI, PA15, SPI0_NSS
					Default: PC10
	PC10	78	I/O	5VT	Alternate: UART3_TX, SDIO_D2, DCI_D8
					Remap: USART2_TX, SPI2_SCK, I2S2_CK, TLI_R2
	50			-: <i>-</i> -	Default: PC11
	PC11	79	I/O	5VT	Alternate: UART3_RX, SDIO_D3, DCI_D4
-					Remap: USART2_RX, SPI2_MISO
	DC40	00	1/0	E\ /T	Default: PC12 Alternate: UART4_TX, SDIO_CK, DCI_D9
	PC12	80	I/O	5VT	Remap: USART2_CK, SPI2_MOSI, I2S2_SD
ŀ					Default: PD0
	PD0	81	I/O	5VT	Alternate: EXMC_D2
	. 50	٥.	,,,	341	Remap: CAN0_BX, OSCIN
ŀ					Default: PD1
	PD1	82	I/O	5VT	Alternate: EXMC_D3
L					<u> </u>





_					GD32F207XX Datastieet
	Pin Name	Pins	Pin	I/O	Functions description
	riii ivaille	FIIIS	Type ⁽¹⁾	Level ⁽²⁾	runctions description
					Remap: CAN0_TX, OSCOUT
	DD 0	00	1/0	5) /T	Default: PD2
	PD2	83	1/0	5VT	Alternate: TIMER2_ETI, UART4_RX, SDIO_CMD, DCI_D11
					Default: PD3
	DDO	84	1/0	5) /T	Alternate: EXMC_CLK
	PD3		I/O	5VT	Remap: USART1_CTS, DCI_D5, TLI_G7, SPI1_SCK,
					12S1_CK
					Default: PD4
	PD4	85	I/O	5VT	Alternate: EXMC_NOE
ļ					Remap: USART1_RTS
					Default: PD5
	PD5	86	I/O	5VT	Alternate: EXMC_NWE
ļ					Remap: USART1_TX
					Default: PD6
	PD6	87	I/O	5VT	Alternate: EXMC_NWAIT
	1 00	01	1/0	3 7 1	Remap: USART1_RX, DCI_D10, TLI_B2, SPI2_MOSI,
					12S2_SD
					Default: PD7
	PD7	88	I/O	5VT	Alternate: EXMC_NE0, EXMC_NCE1
ļ					Remap: USART1_CK
					Default: JTDO
	PB3	89	I/O	5VT	Alternate:SPI2_SCK, I2S2_CK
ļ					Remap: PB3, TRACESWO, TIMER1_CH1, SPI0_SCK
					Default: JNTRST
	PB4	90	I/O	5VT	Alternate: SPI2_MISO
					Remap: TIMER2_CH0, PB4, SPI0_MISO
					Default: PB5
					Alternate: I2C0_SMBA, SPI2_MOSI, I2S2_SD,
	PB5	91	I/O		ENET_PPS_OUT, DCI_D10
					Remap: TIMER2_CH1, SPI0_MOSI, CAN1_RX,
					EXMC_SDCKE1
					Default: PB6
	PB6	92	I/O	5VT	Alternate: I2C0_SCL, TIMER3_CH0, DCI_D5
ļ					Remap: USART0_TX, CAN1_TX, EXMC_SDNE1, SPI0_IO3
					Default: PB7
	PB7	93	I/O	5VT	Alternate: I2C0_SDA , TIMER3_CH1, EXMC_NL,
					DCI_VSYNC
ļ					Remap: USART0_RX, SPI0_IO4
	BOOT0	94	I		Default: BOOT0
					Default: PB8
	PB8	95	I/O	5VT	Alternate: TIMER3_CH2, TIMER9_CH0, ENET_MII_TXD3,
	= +				SDIO_D4, DCI_D6
ļ					Remap: I2C0_SCL, CAN0_RX, TLI_B6
	_				Default: PB9
	PB9	96	I/O	5VT	Alternate: TIMER3_CH3, TIMER10_CH0, SDIO_D5, DCI_D7
					Remap: I2C0_SDA, CAN0_TX, TLI_B7, SPI1_NSS,



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Pin Name	Pins	Pin Type ⁽¹⁾	I/O Level ⁽²⁾	Functions description
				12S1_WS
				Default: PE0
PE0	97	I/O	5VT	Alternate: TIMER3_ETI, EXMC_NBL0, UART7_RX
				Remap: DCI_D2
				Default: PE1
PE1	98	I/O	5VT	Alternate: EXMC_NBL1, UART7_TX
				Remap: DCI_D3
Vss_3	99	Р		Default: Vss_3
V _{DD_3}	100	Р		Default: V _{DD_3}

Notes:

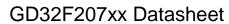
- (1) Type: I = input, O = output, P = power.
- (2) I/O Level: 5VT = 5 V tolerant.



2.6.4. GD32F207Rx LQFP64 pin definitions

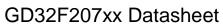
Table 2-6. GD32F207Rx LQFP64 pin definitions

. 4.5.5 _ 5. 5				
Pin Name	Pins	Pin	1/0	Functions description
		Type ⁽¹⁾	Level ⁽²⁾	
V _{BAT}	1	Р		Default: V _{BAT}
PC13-				Default: PC13
TAMPER-	2	I/O	5VT	Alternate: TAMPER-RTC
RTC				Alternate. TAMP EN-KTO
PC14-		1/0		Default: PC14
OSC32IN	3	I/O		Alternate: OSC32IN
PC15-				Default: PC15
OSC32OUT	4	I/O		Alternate: OSC32OUT
				Default: OSCIN
OSCIN	5	I		Remap: PD0
	_	_		Default: OSCOUT
OSCOUT	6	0		Remap: PD1
NRST	7	I/O		Default: NRST
				Default: PC0
PC0	8	I/O		Alternate: ADC012_IN10
				Remap: EXMC_SDNWE
	_			Default: PC1
PC1	9	I/O		Alternate: ADC012_IN11, ENET_MDC
				Default: PC2
PC2	10	I/O		Alternate: ADC012_IN12, ENET_MII_TXD2
				Remap: EXMC_SDNE0, SPI1_MISO
				Default: PC3
PC3	11	I/O		Alternate: ADC012_IN13, ENET_MII_TX_CLK
				Remap: EXMC_SDCKE0, SPI1_MOSI, I2S1_SD
Vssa	12	Р		Default: V _{SSA}
V _{DDA}	13	Р		Default: V _{DDA}
				Default: PA0
				Alternate: WKUP, USART1_CTS, ADC012_IN0,
PA0-WKUP	14	I/O		TIMER1_CH0, TIMER1_ETI, TIMER4_CH0, TIMER7_ETI,
				ENET_MII_CRS
				Remap: UART3_TX
				Default: PA1
PA1	15	I/O		Alternate: USART1_RTS, ADC012_IN1, TIMER1_CH1,
1 71	13	1/0		TIMER4_CH1,ENET_MII_RX_CLK, ENET_RMII_REF_CLK
				Remap: UART3_RX
				Default: PA2
PA2	16	I/O		Alternate: USART1_TX, ADC012_IN2, TIMER1_CH2,
				TIMER4_CH2, TIMER8_CH0, ENET_MDIO, SPI0_IO3
_				Default: PA3
PA3	17	I/O		Alternate: USART1_RX, ADC012_IN3, TIMER1_CH3,
				TIMER4_CH3, TIMER8_CH1, ENET_MII_COL, SPI0_IO4



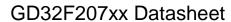


		Din	1/0	ODSZI ZOTAX Datastice
Pin Name	Pins	Pin Type ⁽¹⁾	I/O Level ⁽²⁾	Functions description
		.) 0		Remap: TLI_B5
V _{SS_4}	18	Р		Default: Vss 4
V _{33_4} V _{DD_4}	19	Р		Default: V _{DD} 4
V DD_4	13	'		Default: PA4
				Alternate: SPI0_NSS, USART1_CK, DAC_OUT0,
PA4	20	I/O		ADC01_IN4, DCI_HSYNC
				Remap: SPI2_NSS, I2S2_WS, TLI_VSYNC
				Default: PA5
PA5	21	I/O		Alternate: SPI0_SCK, ADC01_IN5, DAC_OUT1
17.0		1,0		Remap: TIMER1_CH0, TIMER1_ETI, TIMER7_CH0_ON
				Default: PA6
				Alternate: SPI0_MISO, ADC01_IN6, TIMER2_CH0,
PA6	22	I/O		TIMER7_BRKIN, TIMER12_CH0, DCI_PIXCLK
				Remap: TIMER0_BRKIN, TLI_G2
				Default: PA7
				Alternate: SPI0_MOSI, ADC01_IN7, TIMER2_CH1,
PA7	23	I/O		TIMER7_CH0_ON, TIMER13_CH0, ENET_MII_RX_DV,
				ENET_RMII_CRS_DV
				Remap: TIMER0_CH0_ON
				Default: PC4
PC4	24	I/O		Alternate: ADC01_IN14, ENET_MII_RXD0.
				ENET_RMII_RXD0
				Default: PC5
PC5	25	I/O		Alternate: ADC01_IN15, ENET_MII_RXD1,
				ENET_RMII_RXD1
				Default: PB0
PB0	26	I/O		Alternate: ADC01_IN8, TIMER2_CH2, TIMER7_CH1_ON,
1 50	20	1/0		ENET_MII_RXD2
				Remap: TIMER0_CH1_ON, TLI_R3
				Default: PB1
PB1	27	I/O		Alternate: ADC01_IN9, TIMER2_CH3, TIMER7_CH2_ON,
				ENET_MII_RXD3
				Remap: TIMER0_CH2_ON, TLI_R6
PB2	28	I/O	5VT	Default: PB2, BOOT1
			-: <i>-</i> -	Default: PB10
PB10	29	I/O	5VT	Alternate: I2C1_SCL, USART2_TX, ENET_MII_RX_ER
				Remap: TIMER1_CH2, TLI_G4, SPI1_SCK, I2S1_CK
				Default: PB11
PB11	30	I/O	5VT	Alternate: I2C1_SDA, USART2_RX, ENET_MII_TX_EN,
				ENET_RMII_TX_EN Remap: TIMER1_CH3, TLI_G5
Voc.	31	P		Default: Vss_1
V _{SS_1}				Default: V _{DD_1}
V _{DD_1}	32	Р		
PB12	33	I/O	5VT	Default: PB12
				Alternate: SPI1_NSS, I2C1_SMBA, USART2_CK,





					GD32F207XX DataSileet
	Pin Name	Pins	Pin	I/O	Functions description
			Type ⁽¹⁾	Level ⁽²⁾	
					TIMERO_BRKIN, I2S1_WS, CAN1_RX, ENET_MII_TXD0,
-					ENET_RMII_TXD0
	DD 40	0.4	1/0	5) /T	Default: PB13
	PB13	34	I/O	5VT	Alternate: SPI1_SCK, USART2_CTS, TIMER0_CH0_ON,
-					I2S1_CK, CAN1_TX , ENET_MII_TXD1, ENET_RMII_TXD1
	DD4.4	0.5	1/0	5) /T	Default: PB14
	PB14	35	I/O	5VT	Alternate: SPI1_MISO, USART2_RTS, TIMER0_CH1_ON,
-					TIMER11_CH0 Default: PB15
	PB15	36	I/O	5VT	Alternate: SPI1_MOSI, TIMER0_CH2_ON, I2S1_SD,
	FDIS	30	1/0	371	TIMER11_CH1
ŀ					Default: PC6
					Alternate: I2S1_MCK, TIMER7_CH0, SDIO_D6,
	PC6	37	I/O	5VT	USART5_TX
					Remap: TIMER2_CH0, DCI_D0, TLI_HSYNC
ľ					Default: PC7
					Alternate: I2S2_MCK, TIMER7_CH1, SDIO_D7,
	PC7	38	I/O	5VT	USART5_RX
					Remap: TIMER2_CH1, DCI_D1, TLI_G6
-					Default: PC8
	PC8	39	I/O	5VT	Alternate: TIMER7_CH2, SDIO_D0, DCI_D2, USART5_CK
					Remap: TIMER2_CH2
					Default: PC9
	PC9	40	I/O	5VT	Alternate: TIMER7_CH3, SDIO_D1, DCI_D3, CK_OUT1
ļ					Remap: TIMER2_CH3, I2C2_SDA
					Default: PA8
	PA8	41	I/O	5VT	Alternate: USART0_CK, TIMER0_CH0, CK_OUT0, VCORE,
	1710	• •	., 0	011	USBFS_SOF
ļ					Remap: TLI_R6, I2C2_SCL
					Default: PA9
	PA9	42	I/O	5VT	Alternate: USART0_TX, TIMER0_CH1, USBFS_VBUS,
					DCI_D0
ŀ					Remap: I2C2_SMBAI
	PA10	43	I/O	5VT	Default: PA10
-					Alternate: USART0_RX, TIMER0_CH2, USBFS_ID, DCI_D1
					Default: PA11 Alternate: USART0_CTS, CAN0_RX, USBFS_DM,
	PA11	44	I/O	5VT	TIMERO_CH3
					Remap: TLI_R4
ŀ					Default: PA12
					Alternate: USART0_RTS, USBFS_DP, CAN0_TX,
	PA12	45	I/O	5VT	TIMERO_ETI
					Remap: TLI_R5
ŀ					Default: JTMS, SWDIO
	PA13	46	I/O	5VT	Remap: PA13
ľ	Vss_2	47	Р		Default: Vss_2
L					





		Pin	I/O	
Pin Name	Pins	Type ⁽¹⁾	Level ⁽²⁾	Functions description
V_{DD_2}	48	Р		Default: V _{DD_2}
PA14	49	I/O	5VT	Default: JTCK, SWCLK
r A 14	43	1/0	3 7 1	Remap: PA14
				Default: JTDI
PA15	50	I/O	5VT	Alternate: SPI2_NSS, I2S2_WS
				Remap: TIMER1_CH0, TIMER1_ETI, PA15, SPI0_NSS
5040		.,,	-> - -	Default: PC10
PC10	51	I/O	5VT	Alternate: UART3_TX, SDIO_D2, DCI_D8
				Remap: USART2_TX, SPI2_SCK, I2S2_CK, TLI_R2 Default: PC11
PC11	52	I/O	5VT	Alternate: UART3_RX, SDIO_D3, DCI_D4
1011	32	1/0	3 7 1	Remap: USART2_RX, SPI2_MISO
				Default: PC12
PC12	53	I/O	5VT	Alternate: UART4_TX, SDIO_CK, DCI_D9
				Remap: USART2_CK, SPI2_MOSI, I2S2_SD
DD:			-> <i>(</i>	Default: PD2
PD2	54	I/O	5VT	Alternate: TIMER2_ETI, UART4_RX, SDIO_CMD, DCI_D11
				Default: JTDO
PB3	55	I/O	5VT	Alternate:SPI2_SCK, I2S2_CK
				Remap: PB3, TRACESWO, TIMER1_CH1, SPI0_SCK
				Default: JNTRST
PB4	56	I/O	5VT	Alternate: SPI2_MISO
				Remap: TIMER2_CH0, PB4, SPI0_MISO
				Default: PB5
PB5	57	I/O		Alternate: I2C0_SMBA, SPI2_MOSI, I2S2_SD, ENET_PPS_OUT, DCI_D10
PBS	57	1/0		Remap: TIMER2_CH1, SPI0_MOSI, CAN1_RX,
				EXMC_SDCKE1
				Default: PB6
PB6	58	I/O	5VT	Alternate: I2C0_SCL, TIMER3_CH0, DCI_D5
				Remap: USART0_TX, CAN1_TX, EXMC_SDNE1, SPI0_IO3
				Default: PB7
PB7	59	I/O	5VT	Alternate: I2C0_SDA , TIMER3_CH1, EXMC_NL,
PB/	59	1/0	371	DCI_VSYNC
				Remap: USART0_RX, SPI0_IO4
воото	60	I		Default: BOOT0
				Default: PB8
PB8	61	I/O	5VT	Alternate: TIMER3_CH2, TIMER9_CH0, ENET_MII_TXD3,
				SDIO_D4, DCI_D6
				Remap: I2C0_SCL, CAN0_RX, TLI_B6
				Default: PB9
PB9	62	I/O	5VT	Alternate: TIMER3_CH3, TIMER10_CH0, SDIO_D5, DCI_D7 Remap: I2C0_SDA, CAN0_TX, TLI_B7, SPI1_NSS,
				I2S1_WS
V _{SS_3}	63	Р		Default: Vss 3
v SS_3	US	'		Doraum 19979



GD32F207xx Datasheet

Pin Name	Pins	Pin Type ⁽¹⁾	I/O Level ⁽²⁾	Functions description
V_{DD_3}	64	Р		Default: V _{DD_3}

Notes:

- (1) Type: I = input, O = output, P = power.
- (2) I/O Level: 5VT = 5 V tolerant.



3. Functional description

3.1. Arm® Cortex®-M3 core

The Cortex®-M3 processor is the latest generation of Arm® processors for embedded systems. It has been developed to provide a low-cost platform that meets the needs of MCU implementation, with a reduced pin count and low-power consumption, while delivering outstanding computational performance and an advanced system response to interrupts.

- 32-bit Arm® Cortex®-M3 processor core
- Up to 120 MHz operation frequency
- Single-cycle multiplication and hardware divider
- Integrated Nested Vectored Interrupt Controller (NVIC)
- 24-bit SysTick timer

The Cortex®-M3 processor is based on the ARMv7 architecture and supports both Thumb and Thumb-2 instruction sets. Some system peripherals listed below are also provided by Cortex®-M3:

- Internal Bus Matrix connected with ICode bus, DCode bus, system bus, Private Peripheral Bus (PPB) and debug accesses (AHB-AP)
- Nested Vectored Interrupt Controller (NVIC)
- Flash Patch and Breakpoint (FPB)
- Data Watchpoint and Trace (DWT)
- Instrument Trace Macrocell (ITM)
- Memory Protection Unit (MPU)
- Serial Wire JTAG Debug Port (SWJ-DP)
- Trace Port Interface Unit (TPIU)

3.2. On-chip memory

- Up to 3072 Kbytes of flash memory, including code flash and data flash
- Up to 256 Kbytes of SRAM

The Arm® Cortex®-M3 processor is structured in Harvard architecture which can use separate buses to fetch instructions and load/store data. 3072 Kbytes of inner flash at most, which includes code flash and data flash is available for storing programs and data, and accessed (R/W) at CPU clock speed with zero wait states. Up to 256 Kbytes of inner SRAM is composed of SRAM0, SRAM1, and SRAM2 that can be accessed at same time. <u>Table 2-2.</u> <u>GD32F207xx memory map</u> shows the memory map of the GD32F207xx series of devices, including flash, SRAM, peripheral, and other pre-defined regions.



3.3. Clock, reset and supply management

- Internal 8 MHz factory-trimmed RC and external 3 to 25 MHz crystal oscillator
- Internal 40 KHz RC calibrated oscillator and external 32.768 KHz crystal oscillator
- Integrated system clock PLL
- 2.6 to 3.6 V application supply and I/Os
- Supply Supervisor: POR (Power On Reset), PDR (Power Down Reset), and low voltage detector (LVD)

The Clock Control Unit (CCU) provides a range of oscillator and clock functions. These include speed internal RC oscillator and external crystal oscillator, high speed and low speed two types. Several prescalers allow the frequency configuration of the AHB and two APB domains. The maximum frequency of the AHB/APB2/APB1 domains is 120/120/60 MHz. See *Figure 2-6. GD32F207xx clock tree* for details on the clock tree.

The Reset Control Unit (RCU) controls three kinds of reset: system reset resets the processor core and peripheral IP components. Power-on reset (POR) and power-down reset (PDR) are always active, and ensures proper operation starting from 2.6 V and down to 1.8V. The device remains in reset mode when V_{DD} is below a specified threshold. The embedded low voltage detector (LVD) monitors the power supply, compares it to the voltage threshold and generates an interrupt as a warning message for leading the MCU into security.

Power supply schemes:

- V_{DD} range: 2.6 to 3.6 V, external power supply for I/Os and the internal regulator. Provided externally through V_{DD} pins.
- V_{SSA}, V_{DDA} range: 2.6 to 3.6 V, external analog power supplies for ADC, reset blocks, RCs and PLL. V_{DDA} and V_{SSA} must be connected to V_{DD} and V_{SS}, respectively.
- V_{BAT} range: 1.8 to 3.6 V, power supply for RTC, external clock 32 KHz oscillator and backup registers (through power switch) when V_{DD} is not present.

3.4. Boot modes

At startup, boot pins are used to select one of three boot options:

- Boot from main flash memory (default)
- Boot from system memory
- Boot from on-chip SRAM

The boot loader is located in the internal boot ROM memory (system memory). It is used to reprogram the flash memory by using USART0 (PA9 and PA10), USART1 (PD5 and PD6) and USB (PA9, PA10, PA11 and PA12). It also can be used to transfer and update the flash memory code, the data and the vector table sections. In default condition, boot from bank 0 of flash memory is selected. It also supports to boot from bank 1 of flash memory by setting a bit in option bytes.



3.5. Power saving modes

The MCU supports three kinds of power saving modes to achieve even lower power consumption. They are sleep mode, deep-sleep mode, and standby mode. These operating modes reduce the power consumption and allow the application to achieve the best balance between the CPU operating time, speed and power consumption.

■ Sleep mode

In sleep mode, only the clock of CPU core is off. All peripherals continue to operate and any interrupt/event can wake up the system.

■ Deep-sleep mode

In deep-sleep mode, all clocks in the 1.2V domain are off, and all of the high speed crystal oscillator (IRC8M, HXTAL) and PLL are disabled. Only the contents of SRAM and registers are retained. Any interrupt or wakeup event from EXTI lines can wake up the system from the deep-sleep mode including the 16 external lines, the RTC alarm, the LVD output, the Ethernet wakeup and USB wakeup. When exiting the deep-sleep mode, the IRC8M is selected as the system clock.

Standby mode

In standby mode, the whole 1.2V domain is power off, the LDO is shut down, and all of IRC8M, HXTAL and PLL are disabled. The contents of SRAM and registers (except backup registers) are lost. There are four wakeup sources for the standby mode, including the external reset from NRST pin, the RTC alarm, the FWDGT reset, and the rising edge on WKUP pin.

3.6. Analog to digital converter (ADC)

- 12-bit SAR ADC engine with up to 2 MSPS conversion rate
- 12-bit, 10-bit, 8-bit or 6-bit configurable resolution
- Hardware oversampling ratio adjustable from 2 to 256x improves resolution to 16-bit
- Conversion range: V_{SSA} to V_{DDA} (2.6 to 3.6 V)
- Temperature sensor

Up to three 12-bit 2 MSPS multi-channel ADC are integrated in the device. It is a total of up to 16 multiplexed external channels with 2 internal channels for temperature sensor and voltage reference measurement. The conversion range is between 2.6 V < V_{DDA} < 3.6 V. An on-chip 16-bit hardware oversample scheme improves performances while off-loading the related computational burden from the MCU. An analog watchdog block can be used to detect the channels, which are required to remain within a specific threshold window. A configurable channel management block of analog inputs also can be used to perform conversions in single, continuous, scan or discontinuous mode to support more advanced usages.

The ADC can be triggered from the events generated by the general level 0 timers (TIMERx) and the advanced timers (TIMER0 and TIMER7) with internal connection. The temperature sensor can be used to generate a voltage that varies linearly with temperature. It is internally



connected to the ADC_IN16 input channel which is used to convert the sensor output voltage into a digital value.

3.7. Digital to analog converter (DAC)

- 12-bit DAC converter of independent output channel
- 8-bit or 12-bit mode in conjunction with the DMA controller

The 12-bit buffered DAC channel is used to generate variable analog outputs. The DAC is designed with integrated resistor strings structure. The DAC channels can be triggered by the timer update outputs or EXTI with DMA support. The maximum output value of the DAC is $V_{\text{REF+}}$.

3.8. DMA

- 14 channels DMA controller and each channel are configurable (7 for DMA0 and 7 for DMA1)
- Peripherals supported: Timers, ADC, SPIs, I2Cs, USARTs, DAC, I2S, SDIO, DCI, CAU and HAU

The flexible general-purpose DMA controllers provide a hardware method of transferring data between peripherals and/or memory without intervention from the CPU, thereby freeing up bandwidth for other system functions. Three types of access method are supported: peripheral to memory, memory to peripheral, memory to memory.

Each channel is connected to fixed hardware DMA requests. The priorities of DMA channel requests are determined by software configuration and hardware channel number. Transfer size of source and destination are independent and configurable.

3.9. General-purpose inputs/outputs (GPIOs)

- Up to 140 fast GPIOs, all mappable on 16 external interrupt lines
- Analog input/output configurable
- Alternate function input/output configurable

There are up to 140 general purpose I/O pins (GPIO) in GD32F207xx, named PA0 ~ PA15, PB0 ~ PB15, PC0 ~ PC15, PD0 ~ PD15, PE0 ~ PE15, PF0 ~ PF15, PG0 ~ PG15, PH0 ~ PH15 and PI0 ~ PI11 to implement logic input/output functions. Each of the GPIO ports has related control and configuration registers to satisfy the requirements of specific applications. The external interrupts on the GPIO pins of the device have related control and configuration registers in the Interrupt/event controller (EXTI). The GPIO ports are pin-shared with other alternative functions (AFs) to obtain maximum flexibility on the package pins. Each of the GPIO pins can be configured by software as output (push-pull or open-drain), as input (with or without pull-up or pull-down) or as peripheral alternate function. Most of the GPIO pins are



shared with digital or analog alternate functions. All GPIOs are high-current capable except for analog inputs.

3.10. Timers and PWM generation

- Two 16-bit advanced timer (TIMER0 & TIMER7), ten 16-bit general timers (TIMER1 ~ TIMER4, TIMER8 ~ TIMER13), and two 16-bit basic timer (TIMER5 & TIMER6)
- Up to 4 independent channels of PWM, output compare or input capture for each general timer and external trigger input
- 16-bit, motor control PWM advanced timer with programmable dead-time generation for output match
- Encoder interface controller with two inputs using quadrature decoder
- 24-bit SysTick timer down counter
- 2 watchdog timers (free watchdog timer and window watchdog timer)

The advanced timer (TIMER0 & TIMER7) can be used as a three-phase PWM multiplexed on 6 channels. It has complementary PWM outputs with programmable dead-time generation. It can also be used as a complete general timer. The 4 independent channels can be used for input capture, output compare, PWM generation (edge- or center-aligned counting modes) and single pulse mode output. If configured as a 16-bit general timer, it has the same functions as the TIMERx timer. It can be synchronized with external signals or to interconnect with other general timers together which have the same architecture and features.

The general timer, known as TIMER1 ~ TIMER4, TIMER8 ~ TIMER13 can be used for a variety of purposes including general time, input signal pulse width measurement or output waveform generation such as a single pulse generation or PWM output, up to 4 independent channels for input capture/output compare. The general timer is based on a 16-bit auto-reload up/down counter and a 16-bit prescaler. TIMER1 ~ TIMER4 and TIMER8/TIMER11 also supports an encoder interface with two inputs using quadrature decoder.

The basic timer, known as TIMER5 & TIMER6, are mainly used for DAC trigger generation. They can also be used as a simple 16-bit time base.

The GD32F207xx have two watchdog peripherals, free watchdog timer and window watchdog timer. They offer a combination of high safety level, flexibility of use and timing accuracy.

The free watchdog timer includes a 12-bit down-counting counter and an 8-bit prescaler, it is clocked from an independent 40 KHz internal RC and as it operates independently of the main clock, it can operate in deep-sleep and standby modes. It can be used either as a watchdog to reset the device when a problem occurs, or as a free-running timer for application timeout management.

The window watchdog timer is based on a 7-bit down counter that can be set as free-running. It can be used as a watchdog to reset the device when a problem occurs. It is clocked from the main clock. It has an early wakeup interrupt capability and the counter can be frozen in debug mode.



The SysTick timer is dedicated for OS, but could also be used as a standard down counter.

The features are shown below:

- A 24-bit down counter
- Auto reload capability
- Maskable system interrupt generation when the counter reaches 0
- Programmable clock source

3.11. Real time clock (RTC) and backup registers

- 32-bit up-counter with a programmable 20-bit prescaler
- Alarm function
- Interrupt and wake-up event
- 84 bytes backup registers for data protection

The real time clock is an independent timer which provides a set of continuously running counters in backup registers to provide a real calendar function, and provides an alarm interrupt or an expected interrupt. It is not reset by a system or power reset, or when the device wakes up from standby mode. A 20-bit prescaler is used for the time base clock and is by default configured to generate a time base of 1 second from a clock at 32.768 KHz from external crystal oscillator.

The backup registers are located in the backup domain that remains powered-on by V_{BAT} even if V_{DD} power is shut down, they are forty two 16-bit (84 bytes) registers for data protection of user application data, and the wake-up action from standby mode or system reset do not affect these registers.

In addition, the backup registers can be used to implement the tamper detection, RTC calibration function and waveform detection.

3.12. Inter-integrated circuit (I2C)

- Up to three I2C bus interfaces can support both master and slave mode with a frequency up to 400 KHz
- Provide arbitration function, optional PEC (packet error checking) generation and checking
- Supports 7-bit and 10-bit addressing mode and general call addressing mode

The I2C interface is an internal circuit allowing communication with an external I2C interface which is an industry standard two line serial interface used for connection to external hardware. These two serial lines are known as a serial data line (SDA) and a serial clock line (SCL). The I2C module provides transfer rate of up to 100 KHz in standard mode and up to 400 KHz in fast mode. The I2C module also has an arbitration detect function to prevent the situation where more than one master attempts to transmit data to the I2C bus at the same time. A CRC-8 calculator is also provided in I2C interface to perform packet error checking



for I2C data.

3.13. Serial peripheral interface (SPI)

- Up to three SPI interfaces with a frequency of up to 30 MHz
- Support both master and slave mode
- Hardware CRC calculation and transmit automatic CRC error checking
- Quad wire configuration available in master mode (only in SPI0)

The SPI interface uses 4 pins, among which are the serial data input and output lines (MISO & MOSI), the clock line (SCK) and the slave select line (NSS). Both SPIs can be served by the DMA controller. The SPI interface may be used for a variety of purposes, including simplex synchronous transfers on two lines with a possible bidirectional data line or reliable communication using CRC checking. Quad-SPI master mode is also supported in SPIO.

3.14. Universal synchronous/asynchronous receiver transmitter (USART/UART)

- Up to four USARTs and four UARTs with operating frequency up to 7.5 MHz
- Supports both asynchronous and clocked synchronous serial communication modes
- IrDA SIR encoder and decoder support
- LIN break generation and detection
- ISO 7816-3 compliant smart card interface

The USART (USART0, USART1, USART2, USART5) and UART (UART3, UART4, UART6, UART7) are used to transmit data between parallel and serial interfaces, provides a flexible full duplex data exchange using synchronous or asynchronous transfer. It is also commonly used for RS-232 standard communication. The USART/UART includes a programmable baud rate generator which is capable of dividing the system clock to produce a dedicated clock for the USART/UART transmitter and receiver. The USART/UART also supports DMA function for high speed data communication.

3.15. Inter-IC sound (I2S)

- Two I2S bus Interfaces with sampling frequency from 8 KHz to 192 KHz, multiplexed with SPI1 and SPI2
- Support either master or slave mode audio
- Sampling frequencies from 8 KHz up to 192 KHz are supported.

The Inter-IC sound (I2S) bus provides a standard communication interface for digital audio applications by 3-wire serial lines. GD32F207xx contain an I2S-bus interface that can be operated with 16/32-bit resolution in master or slave mode, pin multiplexed with SPI1 and



SPI2. The audio sampling frequencies from 8 KHz to 192 KHz is supported with less than 0.5% accuracy error.

3.16. Universal serial bus full-speed interface (USBFS)

- One USB device/host full-speed Interface with frequency up to 12 Mbit/s
- Internal main PLL for USB CLK compliantly

The Universal Serial Bus (USB) is a 4-wire bus with 4 bidirectional endpoints. The device controller enables 12 Mbit/s data exchange with integrated transceivers in device/host mode. Full-speed peripheral is compliant with the USB 2.0 specification. Transaction formatting is performed by the hardware, including CRC generation and checking. The status of a completed USB transfer or error condition is indicated by status registers. An interrupt is also generated if enabled. The dedicated 48 MHz clock is generated from the internal main PLL (the clock source must use a HXTAL crystal oscillator) and the operating frequency divided from APB1 should be 12 MHz above.

3.17. Controller area network (CAN)

- Two CAN2.0B interface with communication frequency up to 1 Mbit/s
- Internal main PLL for CAN CLK compliantly

Controller area network (CAN) is a method for enabling serial communication in field bus. The CAN protocol has been used extensively in industrial automation and automotive applications. It can receive and transmit standard frames with 11-bit identifiers as well as extended frames with 29-bit identifiers. Each CAN has three mailboxes for transmission and two FIFOs of three message deep for reception. It also provides 28 scalable/configurable identifier filter banks for selecting the incoming messages needed and discarding the others.

3.18. Ethernet (ENET)

- IEEE 802.3 compliant media access controller (MAC) for Ethernet LAN
- 10/100 Mbit/s rates with dedicated DMA controller and SRAM
- Support hardware precision time protocol (PTP) with conformity to IEEE 1588

The Ethernet media access controller (MAC) conforms to IEEE 802.3 specifications and fully supports IEEE 1588 standards. The embedded MAC provides the interface to the required external network physical interface (PHY) for LAN bus connection via an internal media independent interface (MII) or a reduced media independent interface (RMII). The number of MII signals provided up to 16 with 25 MHz output and RMII up to 7 with 50 MHz output. The function of 32-bit CRC checking is also available.



3.19. External memory controller (EXMC)

- Supported external memory: SRAM, PSRAM, ROM and NOR-Flash, NAND Flash and PC card, SDRAM with up to 32-bit data bus
- Provide ECC calculating hardware module for NAND Flash memory block
- Two SDRAM banks with independent configuration, up to 13-bits Row Address, 11-bits Column Address, 2-bits internal banks address
- SDRAM Memory size: 4x16Mx32bit(256 MB), 4x16Mx16bit (128 MB), 4x16Mx8bit (64 MB)

External memory controller (EXMC) is an abbreviation of external memory controller. It is divided into several sub-banks for external device support, each sub-bank has its own chip selection signal but at one time, only one bank can be accessed. The EXMC support code execution from external memory except NAND Flash and PC card. The EXMC also can be configured to interface with the most common LCD module of Motorola 6800 and Intel 8080 series and reduce the system cost and complexity.

The EXMC of GD32F207xx in LQFP144 package above also supports synchronous dynamic random access memory (SDRAM). It translates AHB transactions into the appropriate SDRAM protocol, and meanwhile, makes sure the access time requirements of the external SDRAM devices are satisfied.

3.20. Secure digital input and output card interface (SDIO)

■ Support SD2.0/SDIO2.0/MMC4.2 host interface

The Secure Digital Input and Output Card Interface (SDIO) provides access to external SD memory cards specifications version 2.0, SDIO card specification version 2.0 and multi-media card system specification version 4.2 with DMA supported. In addition, this interface is also compliant with CE-ATA digital protocol rev1.1.

3.21. TFT LCD interface (TLI)

- 24-bit RGB Parallel Pixel Output; 8 bits-per-pixel (RGB888)
- Supports up to SVGA (800x600) resolution

The TFT LCD interface provides a parallel digital RGB (Red, Green, Blue) and signals for horizontal, vertical synchronization, pixel clock and data enable as output to interface directly to a variety of LCD (Liquid Crystal Display) and TFT (Thin Film Transistor) panels. A built-in DMA engine continuously move data from system memory to TLI and then, output to an external LCD display. Two separate layers are supported in TLI, as well as layer window and blending function.



3.22. Digital camera interface (DCI)

- Digital video/picture capture
- 8/10/12/14 data width supported
- High transfer efficiency with DMA interface
- Video/picture crop supported
- Various pixel formats supported including JPEG/YCrCb/RGB
- Hard/embedded synchronous signals supported

DCI is an 8-bit to 14-bit parallel interface that able to capture video or picture from a camera via Digital Camera Interface. It supports 8/10/12/14 bits data width through DMA operation.

3.23. Cryptographic acceleration Unit (CAU)

- Supports DES, 3DES or AES algorithm
- DES/3DES supports Electronic codebook (ECB) or Cipher block chaining (CBC) mode
- 3DES supports 64bits-key, 128bits-key or 192bits-key
- AES supports 128bits-key, 192bits-key or 256 bits-key
- AES supports Electronic codebook (ECB), Cipher block chaining (CBC) mode or Counter mode (CTR) mode
- Support DMA mode for input data flow

The Cryptographic Acceleration Unit supports acceleration of DES, 3DES or AES (128, 192, or 256) algorithms. The DES/3DES supports Electronic codebook (ECB) or Cipher block chaining (CBC) mode. The AES supports Electronic codebook (ECB), Cipher block chaining (CBC) mode or Counter mode (CTR) mode.

3.24. Hash acceleration unit (HAU)

- Supports SHA-1, SHA-224 and SHA-256 algorithms, compliant with FIPS PUB 180-2 (Federal Information Processing Standards Publication 180-2)
- Supports MD5 compliant with IETF RFC 1321 (Internet Engineering Task Force Request For Comments number 1321)
- Supports HMAC (keyed-hash message authentication code) algorithm
- Automatic swapping to comply with the big-endian or little-endian for MD5, SHA-1, SHA-224 and SHA-256 algorithms
- Automatic padding to fit module 512
- Support DMA mode for input data flow

The HAU supports acceleration of SHA-1, SHA-224, SHA-256, MD5 algorithm and the HMAC (keyed-hash message authentication code) algorithm, which calling the SHA-1, SHA-224, SHA-256 or MD5 hash function to calculate key, message, digest three times.



3.25. True Random number generator (TRNG)

- About 40 period PLL clock consumed between two consecutive random numbers
- Disable TRNG module will reduce the chip power consumption
- 32-bit random value seed is generated from analog noise

The true random number generator (TRNG) module can generate a 32-bit value using continuous analog noise.

3.26. Debug mode

■ Serial wire JTAG debug port (SWJ-DP)

The Arm® SWJ-DP Interface is embedded and is a combined JTAG and serial wire debug port that enables either a serial wire debug or a JTAG probe to be connected to the target.

3.27. Package and operation temperature

- LQFP176 (GD32F207Ix), LQFP144 (GD32F207Zx), LQFP100 (GD32F207Vx), LQFP64 (GD32F207Rx)
- Operation temperature range: -40°C to +85°C (industrial level)



4. Electrical characteristics

4.1. Absolute maximum ratings

The maximum ratings are the limits to which the device can be subjected without permanently damaging the device. Note that the device is not guaranteed to operate properly at the maximum ratings. Exposure to the absolute maximum rating conditions for extended periods may affect device reliability.

Table 4-1. Absolute maximum ratings

Symbol	Parameter	Min	Max	Unit
V_{DD}	External voltage range	V _{SS} - 0.3	V _{SS} + 3.6	V
V_{DDA}	External analog supply voltage	V _{SSA} - 0.3	V _{SSA} + 3.6	V
V _{BAT}	External battery supply voltage	V _{SS} - 0.3	V _{SS} + 3.6	V
VIN	Input voltage on 5V tolerant pin	V _{SS} - 0.3	V _{DD} + 4.0	V
VIN	Input voltage on other I/O	V _{SS} - 0.3	4.0	V
lio	Maximum current for GPIO pins	_	25	mA
I _{INJ}	Injected current on 5V tolerant pin	_	±5	mA
IINJ	Injected current on other I/O	_	±5	mA
∑l _{INJ}	Injected current on all I/O	_	±25	mA
TA	Operating temperature range	-40	+85	ů
T _{STG}	Storage temperature range	-55	+150	°C
TJ	Maximum junction temperature	_	125	°C

4.2. Recommended DC characteristics

Table 4-2. DC operating conditions

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{DD}	Supply voltage	_	2.6	3.3	3.6	V
V _{DDA}	Analog supply voltage	Same as V _{DD}	2.6	3.3	3.6	V
V _{BAT}	Battery supply voltage	_	1.8	_	3.6	V

4.3. Power consumption

The power measurements specified in the tables represent that code with data executing from on-chip Flash with the following specifications.

Table 4-3. Power consumption characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I _{DD+} I _{DDA}	Supply current	V _{DD} =V _{DDA} =3.3V, HXTAL=25MHz, System clock=120		130.1		mA
TOD+ TODA	(Run mode)	MHz, All peripherals enabled		5		



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Symbo	Parameter	Conditions	Min	Тур	Max	Unit
		V _{DD} =V _{DDA} =3.3V, HXTAL=25MHz, System clock =120		56.43		mA
		MHz, All peripherals disabled		001.10		
		V _{DD} =V _{DDA} =3.3V, HXTAL=25MHz, System clock=108		117.4		mA
		MHz, All peripherals enabled		5		, (
		V _{DD} =V _{DDA} =3.3V, HXTAL=25MHz, System clock =108		51.07	-	mΑ
		MHz, All peripherals disabled		0		,
		V _{DD} =V _{DDA} =3.3V, HXTAL=25MHz, System clock		79.03		mΑ
		=72MHz, All peripherals enabled				
		V _{DD} =V _{DDA} =3.3V, HXTAL=25MHz, System Clock =72	_	35.05	_	mΑ
		MHz, All peripherals disabled				
		V _{DD} =V _{DDA} =3.3V, HXTAL=8MHz, CPU clock off,		93.05	_	mΑ
	Supply current	System clock=120 MHz, All peripherals enabled				
	(Sleep mode)	V _{DD} =V _{DDA} =3.3V, HXTAL=8MHz, CPU clock off,	_	12.54	_	mΑ
		System clock=120 MHz, All peripherals disabled				
		V _{DD} =V _{DDA} =3.3V, Regulator in Run mode, IRC40K on,		1.21	_	mΑ
	Supply current	RTC on, All GPIOs analog mode				
	(Deep-Sleep	V _{DD} =V _{DDA} =3.3V, Regulator in Low Power mode,		1.18	_	mΑ
	mode)	IRC40K on, RTC on, All GPIOs analog mode				
		V _{DD} =V _{DDA} =3.3V, Regulator in Run mode, IRC40K off,	_	1.02	6.7	mΑ
		RTC off, All GPIOs analog mode				
	Supply current	V _{DD} =V _{DDA} =3.3V, LXTAL off, IRC40K on, RTC on	_	7.49	_	μΑ
	(Standby	V _{DD} =V _{DDA} =3.3V, LXTAL off, IRC40K on, RTC off	_	7.18	_	μΑ
	mode)	V _{DD} =V _{DDA} =3.3V, LXTAL off, IRC40K off, RTC off	—	6.02	22	μΑ
		V _{BAT} =3.6V, LXTAL on, RTC on, LXTAL High driving	_	2.77	_	μΑ
		V _{BAT} =3.3V, LXTAL on, RTC on, LXTAL High driving	_	2.48	_	μΑ
		V _{BAT} =2.6V, LXTAL on, RTC on, LXTAL High driving	_	1.86	_	μΑ
		V _{BAT} =3.6V, LXTAL on, RTC on, LXTAL Mid High		1.11		μΑ
		driving				F
		V _{BAT} =3.3V, LXTAL on, RTC on, LXTAL Mid High	_	1.04		μΑ
	Battery supply	driving				I
I _{BAT}	current	V _{BAT} =2.6V, LXTAL on, RTC on, LXTAL Mid High		0.93	_	μΑ
		driving				'
		V _{BAT} =3.6V, LXTAL on, RTC on, LXTAL Mid Low	_	0.84	_	μΑ
		driving				•
		V _{BAT} =3.3V, LXTAL on, RTC on, LXTAL Mid Low	_	0.77	_	μΑ
		driving				
		V _{BAT} =2.6V, LXTAL on, RTC on, LXTAL Mid Low	_	0.63	_	μΑ
		driving				

4.4. EMC characteristics

EMS (electromagnetic susceptibility) includes ESD (Electrostatic discharge, positive and



negative) and FTB (Burst of Fast Transient voltage, positive and negative) testing result is given in <u>Table 4-4. EMS characteristics</u>, based on the EMS levels and classes compliant with IEC 61000 series standard.

Table 4-4. EMS characteristics

Symbol	Parameter	Conditions	Level/Class
\/	Voltage applied to all device pins to	V _{DD} = 3.3 V, T _A = +25 °C	20
V _{ESD}	induce a functional disturbance	conforms to IEC 61000-4-2	3B
	Fast transient voltage burst applied to	V 22 V T. 125 °C	
V _{FTB}	induce a functional disturbance through	V _{DD} = 3.3 V, T _A = +25 °C	4A
	100 pF on V_{DD} and V_{SS} pins	conforms to IEC 61000-4-4	

EMI (Electromagnetic Interference) emission testing result is given in <u>Table 4-5. EMI</u> <u>characteristics</u>, compliant with IEC 61967-2 standard which specifies the test board and the pin loading.

Table 4-5. EMI characteristics

Symbol Parameter		Conditions			Conditions			
		frequency band	56M	72M	120M			
		$V_{DD} = 3.3 \text{ V},$	0.1 to 2 MHz	<0	<0	<0		
		$T_A = +25 ^{\circ}C$,	2 to 30 MHz	-3.7	-2.8	-1.8		
S _{EMI}	Peak level	compliant with IEC	30 to 130 MHz	-6.5	-8	-5.3	dBµV	
		61967-2	130 MHz to 1GHz	-7	-7	-5		

4.5. Power supply supervisor characteristics

Table 4-6. Power supply supervisor characteristics

		,				
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{POR}	Power on reset threshold		2.32	2.40	2.48	V
V_{PDR}	power down reset threshold		1.72	1.80	1.88	V
V _{HYST}	PDR hysteresis		_	0.6	_	V
T _{RSTTEMP}	Reset temporization		_	2	_	ms

4.6. Electrical sensitivity

The device is strained in order to determine its performance in terms of electrical sensitivity. Electrostatic discharges (ESD) are applied directly to the pins of the sample. Static latch-up (LU) test is based on the two measurement methods.



Table 4-7. ESD characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
\/	Electrostatic discharge	T _A =25 °C; JESD22-			F000	V
VESD(HBM)	voltage (human body model)	A114		_	5000	V
V	Electrostatic discharge	T _A =25 °C;			500	V
V _{ESD(CDM)}	voltage (charge device model)	JESD22-C101		_	500	V

Table 4-8. Static latch-up characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
	I-test	T 05 %C, JEODZO	_	_	±100	mA
LU	V _{supply} over voltage	T _A =25 °C; JESD78	_	_	5.4	V

4.7. External clock characteristics

Table 4-9. High speed external clock (HXTAL) generated from a crystal/ceramic characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
f HXTAL	High Speed External oscillator	Vpp=3.3V	4	8	32	MHz
IHXTAL	(HXTAL) frequency	VDD=3.3V	4	0	32	IVITIZ
C	Recommended load capacitance			20	30	n E
C _{HXTAL}	on OSCIN and OSCOUT	_	_	20	30	pF
	Recommended external feedback					
RFHXTAL	resistor between XTALIN and	_	_	1	_	МΩ
	XTALOUT					
D _{HXTAL}	HXTAL oscillator duty cycle	_	48	50	52	%
IDDHXTAL	HXTAL oscillator operating current	V _{DD} =3.3V, T _A =25°C	_	_	1.2	μA
tsuhxtal	HXTAL oscillator startup time	V _{DD} =3.3V, T _A =25°C	_	2	_	ms

Table 4-10. Low speed external clock (LXTAL) generated from a crystal/ceramic characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
f _{LXTAL}	Low Speed External oscillator (LXTAL) frequency	V _{DD} =V _{BAT} =3.3V	l	32.768	1000	KHz
CLXTAL	Recommended load capacitance on OSC32IN and OSC32OUT		8	10	15	pF
RFLXTAL	Recommended external feedback resistor between XTAL32IN and XTAL32OUT	ı		5		МΩ
D _L XTAL	LXTAL oscillator duty cycle		48	50	52	%
IDDLXTAL	LXTAL oscillator operating current	V _{DD} =V _{BAT} =3.3V	_	10	_	μA



tsulxtal	LXTAL oscillator startup time	V _{DD} =V _{BAT} =3.3V		3		s	
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4.8. Internal clock characteristics

Table 4-11. High speed internal clock (IRC8M) characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
	High Speed Internal					
f _{IRC8M}	Oscillator (IRC8M)	V _{DD} =3.3V	_	8	_	MHz
	frequency					
	IRC8M oscillator Frequency accuracy, Factory-trimmed	V _{DD} =3.3V, T _A =-40°C ~+105°C	-2.5	_	+1.5	%
ACC _{IRC8M}		V _{DD} =3.3V, T _A =0°C ~ +85°C	-1.2	_	+1.2	%
		V _{DD} =3.3V, T _A =25°C	-1	_	+1	%
DIRC8M	IRC8M oscillator duty cycle	V _{DD} =3.3V, f _{IRC8M} =8MHz	48	50	52	%
1	IRC8M oscillator operating	V _{DD} =3.3V, f _{IRC8M} =8MHz		80	100	
IDDIRC8M	current	VDD=3.3 V, IIRC8M=OIVIFIZ		80	100	μΑ
tourpoor	IRC8M oscillator startup	\/pp=2 2\/ fincou=9MUz	1		2	ш
tsuirc8M	time	V _{DD} =3.3V, f _{IRC8M} =8MHz	1		2	us

Table 4-12. Low speed internal clock (IRC40K) characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
firc40K	Low Speed Internal oscillator (IRC40K) frequency	V _{DD} =V _{BAT} =3.3V, T _A =-40°C ~ +85°C	30	40	60	KHz
Iddirc40k	IRC40K oscillator operating current	V _{DD} =V _{BAT} =3.3V, T _A =25°C		1	2	μΑ
tsuirc40k	IRC40K oscillator startup time	V _{DD} =V _{BAT} =3.3V, T _A =25°C	_	_	80	μs

4.9. PLL characteristics

Table 4-13. PLL characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
f _{PLLIN}	PLL input clock frequency		1	8	25	MHz
f _{PLL}	PLL output clock frequency		16	_	120	MHz
tLOCK	PLL lock time				100	μs

4.10. Memory characteristics

Table 4-14. Flash memory characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
PEcyc	Number of guaranteed program /erase cycles before failure (Endurance)	T _A =-40°C ~ +85°C	100	_		kcycles

65

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t _{RET}	Data retention time	T _A =125°C	20			years
tprog	Word programming time	T _A =-40°C ~ +85°C	200		400	us
terase	Page erase time	T _A =-40°C ~ +85°C	60	100	450	ms
tmerase	Mass erase time	T _A =-40°C ~ +85°C	3.2		9.6	S

4.11. **GPIO** characteristics

Table 4-15. I/O port characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
	Standard IO Low level	Vpp=2.6V	-0.3		0.95	V
VIL	input voltage	V DD=2.0 V	-0.3		0.95	V
VIL	5V-tolerant IO Low level	Vpp=2.6V	-0.3		0.9	V
	input voltage	V DD=2.0 V	-0.3	_	0.9	V
	Standard IO High level	Vpp=2.6V	1.2		4.0	V
VIH	input voltage	V DD=2.0 V	1.2		4.0	V
VIH	5V-tolerant IO High level	Vpp=2.6V	1.5		5.5	V
	input voltage	V DD=2.0 V	1.5		5.5	V
VoL	Low level output voltage	V _{DD} =2.6V	_	_	0.2	V
Vон	High level output voltage	V _{DD} =2.6V	2.3	_	_	V
R _{PU}	Internal pull-up resistor	V _{IN} =V _{SS}	30	40	50	kΩ
R _{PD}	Internal pull-down resistor	V _{IN} =V _{DD}	30	40	50	kΩ

4.12. ADC characteristics

Table 4-16. ADC characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{DDA}	Operating voltage		2.6	3.3	3.6	V
VIN	ADC input voltage range		0	_	V _{REF+}	V
f _{ADC}	ADC clock		0.6	_	28	MHz
fs	Sampling rate	12-bit	_	_	2	MHz
R _{ADC}	Input sampling switch resistance		_	_	0.45	kΩ
CADC	Input sampling capacitance	No pin/pad capacitance included	_	6.4	_	pF
tsu	Startup time		_	_	1	μs



4.13. DAC characteristics

Table 4-17. DAC characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{DDA}	Operating voltage		2.6	3.3	3.6	V
VDACIN	DAC input voltage range		0	_	V_{REF+}	V
R _{LOAD}	Load resistance	Resistive load vs. V _{SSA} with buffer ON	5	_	_	kΩ
C _{LOAD}	Load capacitance	No pin/pad capacitance included			50	pF
DNE	Differential non-linearity error	DAC in 12-bit			±3	LSB
INL	Integral non-linearity	DAC in 12-bit	_	_	±4	LSB
Offset	Offset error	DAC in 12-bit, $V_{REF+} = 3.6 \text{ V}$		_	±12	LSB
GE	Gain error	DAC in 12-bit	_	_	±0.5	%

4.14. I2C characteristics

Table 4-18. I2C characteristics

Symbol	Parameter	Conditions	Standard mode		Fast r	Unit	
			Min	Max	Min	Max	Oilit
fscL	SCL clock frequency		0	100	0	400	KHz
t _{SCL(H)}	SCL clock high time		4.0	_	0.6	_	ns
t _{SCL(L)}	SCL clock low time		4.7	_	1.3	_	ns



4.15. SPI characteristics

Table 4-19. Standard SPI characteristics

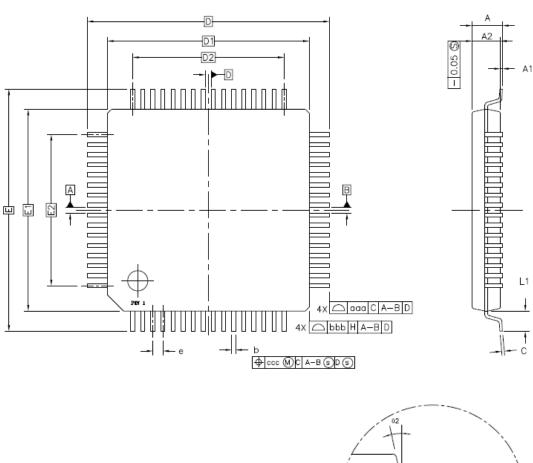
Symbol	Parameter	Conditions	Min	Тур	Max	Unit				
fsck	SCK clock frequency			_	30	MHz				
tsck(H)	SCK clock high time		19	_	_	ns				
t _{SCK(L)}	SCK clock low time		19	_	_	ns				
SPI master mode										
tv(MO)	Data output valid time			_	25	ns				
t _{H(MO)}	Data output hold time		2	_	_	ns				
tsu(MI)	Data input setup time		5	_	_	ns				
t _{H(MI)}	Data input hold time		5	_	_	ns				
		SPI slave mode								
tsu(NSS)	NSS enable setup time	f _{PCLK} =54MHz	74	_	_	ns				
t _{H(NSS)}	NSS enable hold time	f _{PCLK} =54MHz	37	_	_	ns				
t _{A(SO)}	Data output access time	f _{PCLK} =54MHz	0	_	55	ns				
t _{DIS(SO)}	Data output disable time		3	_	10	ns				
tv(so)	Data output valid time		_	_	25	ns				
t _{H(SO)}	Data output hold time		15	_	_	ns				
t _{SU(SI)}	Data input setup time		5	_	_	ns				
t _{H(SI)}	Data input hold time		4	_		ns				



5. Package information

5.1. LQFP package outline dimensions

Figure 5-1. LQFP package outline



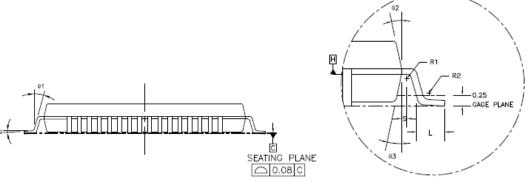




Table 5-1. LQFP package dimensions

	LQFP64			LQFP100			LQFP144			LQFP176		
Symbol	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max
А	-	-	1.60	-	-	1.60	-	-	1.60			1.60
A1	0.05	-	0.15	0.05	-	0.15	0.05	-	0.15	0.05	-	0.15
A2	1.35	1.40	1.45	1.35	1.40	1.45	1.35	1.40	1.45	1.35	1.40	1.45
D	1	12.00	ı	-	16.00	ı	-	22.00	1	1	26.00	
D1	-	10.00	-	-	14.00	-	-	20.00	-	-	24.00	-
Е	1	12.00	ı	-	16.00	ı	-	22.00	1	1	26.00	ı
E1	ı	10.00	ı	-	14.00	ı	-	20.00	ı	ı	24.00	ı
R1	0.08	-	ı	0.08	-	ı	0.08	-	ı	0.08	-	ı
R2	0.08	-	0.20	0.08	-	0.20	0.08	-	0.20	0.08	-	0.20
θ	0°	3.5°	7°	0°	3.5°	7°	0°	3.5°	7°	0°	3.5°	7°
θ1	0°	-	-	0°	-	-	0°	-	-	0°	-	
θ2	11°	12°	13°	11°	12°	13°	11°	12°	13°	11°	12°	13°
θ3	11°	12°	13°	11°	12°	13°	11°	12°	13°	11°	12°	13°
С	0.09	-	0.20	0.09	-	0.20	0.09	-	0.20	0.09	-	0.20
L	0.45	0.60	0.75	0.45	0.60	0.75	0.45	0.60	0.75	0.45	0.60	0.75
L1	-	1.00	ı	-	1.00	ı	-	1.00	-	-	1.00	ı
S	0.20	-	ı	0.20	-	ı	0.20	-	ı	0.20	-	ı
b	0.17	0.20	0.27	0.17	0.20	0.27	0.17	0.20	0.27	0.17	0.20	0.27
е	1	0.50	ı	-	0.50	ı	-	0.50	1	1	0.50	ı
D2	-	7.50	-	-	12.00	•	-	17.50	-	-	21.50	-
E2	-	7.50	-	-	12.00	•	-	17.50	-	-	21.50	-
aaa	0.20			0.20			0.20			0.20		
bbb	0.20			0.20			0.20			0.20		
CCC	0.08		0.08			0.08			0.08			

(Original dimensions are in millmeters)



6. Ordering information

Table 6-1. Part ordering code for GD32F207xx devices

Ordering code	Flash (KB)	Package	Package type	Temperature operating range
GD32F207RCT6	256	LQFP64	Green	Industrial -40°C to +85°C
GD32F207RET6	512	LQFP64	Green	Industrial -40°C to +85°C
GD32F207RGT6	1024	LQFP64	Green	Industrial -40°C to +85°C
GD32F207RKT6	3072	LQFP64	Green	Industrial -40°C to +85°C
GD32F207VCT6	256	LQFP100	Green	Industrial -40°C to +85°C
GD32F207VET6	512	LQFP100	Green	Industrial -40°C to +85°C
GD32F207VGT6	1024	LQFP100	Green	Industrial -40°C to +85°C
GD32F207VKT6	3072	LQFP100	Green	Industrial -40°C to +85°C
GD32F207ZCT6	256	LQFP144	Green	Industrial -40°C to +85°C
GD32F207ZET6	512	LQFP144	Green	Industrial -40°C to +85°C
GD32F207ZGT6	1024	LQFP144	Green	Industrial -40°C to +85°C
GD32F207ZKT6	3072	LQFP144	Green	Industrial -40°C to +85°C
GD32F207IET6	512	LQFP176	Green	Industrial -40°C to +85°C
GD32F207IGT6	1024	LQFP176	Green	Industrial -40°C to +85°C
GD32F207IKT6	3072	LQFP176	Green	Industrial -40°C to +85°C



7. Revision history

Table 7-1. Revision history

Revision No.	Description	Date
1.0	Initial Release	Jul. 10, 2015
2.0	Adapt To New Name Convention	Jan. 24, 2018
2.1	Change pin definitions	Dec. 7, 2018
2.2	Modify the clock tree	Nov. 30, 2019
2.3	1.Modify the HXTAL frequency range of the clock tree to 4-32MHz. 2.The ADC2 mapping function corresponding to PF3, PF4 and PF5 pins is modified to multiplexing function.	Mar.13, 2020
2.4	Modify the <u>Table 4-3. Power consumption characteristics.</u> Add test conditions and parameters in Deep-Sleep and Standby mode	Jun.1, 2021



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